SSD1306

Advance Information

128 x 64 Dot Matrix **OLED/PLED Segment/Common Driver with Controller**

This document contains information on a new product. Specifications and information herein are subject to change without notice.



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1 GENERAL DESCRIPTION

SSD1306 is a single-chip CMOS OLED/PLED driver with controller for organic / polymer light emitting diode dot-matrix graphic display system. It consists of 128 segments and 64commons. This IC is designed for Common Cathode type OLED panel.

The SSD1306 embeds with contrast control, display RAM and oscillator, which reduces the number of external components and power consumption. It has 256-step brightness control. Data/Commands are sent from general MCU through the hardware selectable 6800/8000 series compatible Parallel Interface, I²C interface or Serial Peripheral Interface. It is suitable for many compact portable applications, such as mobile phone sub-display, MP3 player and calculator, etc.

2 FEATURES

- Resolution: 128 x 64 dot matrix panel
- Power supply
 - \circ V_{DD} = 1.65V to 3.3V for IC logic
 - o $V_{CC} = 7V$ to 15V for Panel driving
- For matrix display
 - o OLED driving output voltage, 15V maximum
 - o Segment maximum source current: 100uA
 - Common maximum sink current: 15mA
 - o 256 step contrast brightness current control
- Embedded 128 x 64 bit SRAM display buffer
- Pin selectable MCU Interfaces:
 - 8-bit 6800/8080-series parallel interface
 - o 3 /4 wire Serial Peripheral Interface
 - o I²C Interface
- Screen saving continuous scrolling function in both horizontal and vertical direction
- RAM write synchronization signal
- Programmable Frame Rate and Multiplexing Ratio
- Row Re-mapping and Column Re-mapping
- On-Chip Oscillator
- Chip layout for COG & COF
- Wide range of operating temperature: -40°C to 85°C

3 ORDERING INFORMATION

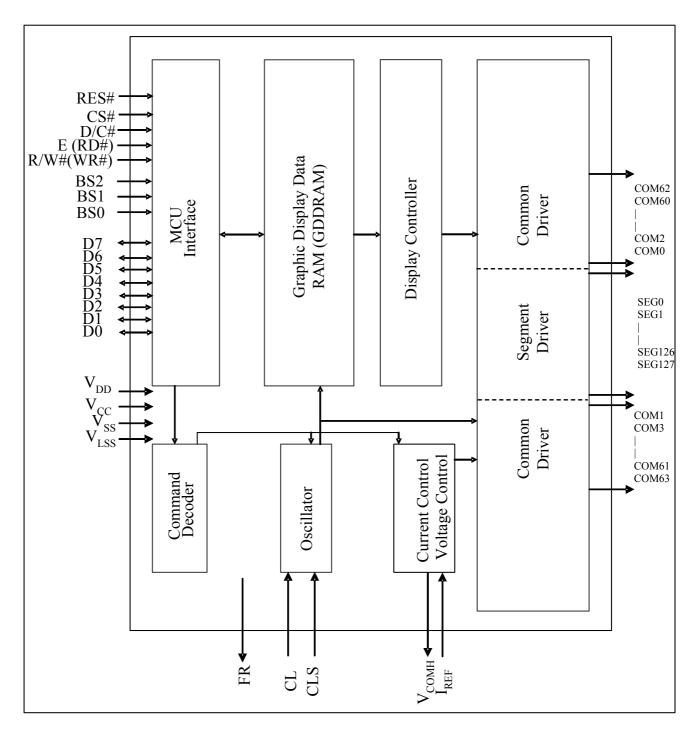
Table 3-1: Ordering Information

Ordering Part Number	SEG	COM	Package Form	Reference	Remark
SSD1306Z	128	64	COG	8	 Min SEG pad pitch: 47um Min COM pad pitch: 40um Die thickness: 300 +/- 25um
SSD1306TR1	104	48	TAB	11, 56	 35mm film, 4 sprocket hole, Folding TAB 8-bit 80 / 8-bit 68 / SPI / I²C interface SEG, COM lead pitch 0.1mm x 0.997 =0.0997mm Die thickness: 457 +/- 25um

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4 BLOCK DIAGRAM

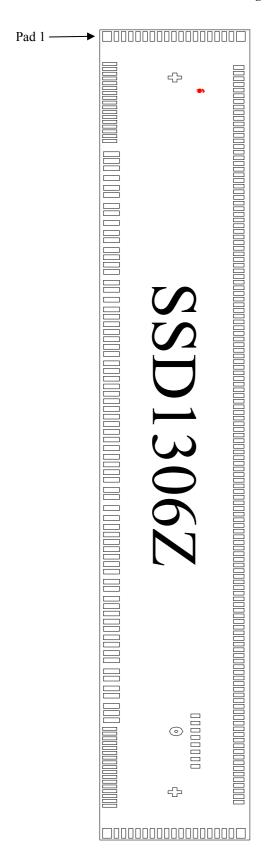
Figure 4-1 SSD1306 Block Diagram



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DIE PAD FLOOR PLAN 5

Figure 5-1: SSD1306Z Die Drawing



Die size	6.76mm x 0.86mm
Die thickness	300 +/- 25um
Min I/O pad pitch	60um
Min SEG pad pitch	47um
Min COM pad pitch	40um
Bump height	Nominal 15um

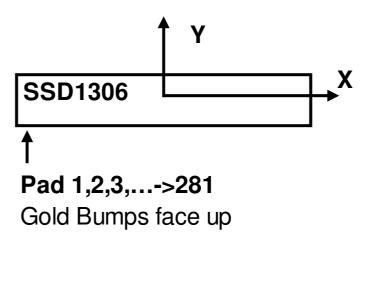
Bump size	
Pad 1, 106, 124, 256	80um x 50um
Pad 2-18, 89-105, 107-123, 257-273	25ium x 80um
Pad 19-88	40um x 89um
Pad 125-255	31um x 59um
Pad 274-281 (TR pads)	30um x 50um

Alignment mark	Position	Size
+ shape	(-2973, 0)	75um x 75um
+ shape	(2973, 0)	75um x 75um
Circle	(2466.665, 7.575)	R37.5um, inner 18um
SSL Logo	(-2862.35, 144.82)	-

(For details dimension please see p.9)

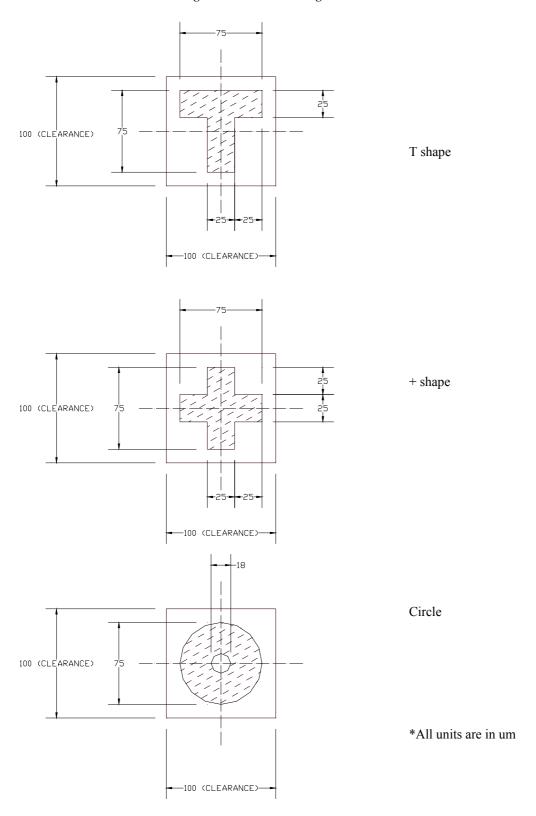
- **Note**(1) Diagram showing the Gold bumps face up.
- (2) Coordinates are referenced to center of the chip.
- Coordinate units and size of all alignment marks are in um.

 (4) All alignment keys do not contain gold



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Figure 5-2: SSD1306Z alignment mark dimensions



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Table 5-1 : SSD1306Z Bump Die Pad Coordinates

| Pad Name | X-pos | Y-pos | Pad no. | Pad Name | X-pos | Y-pos |

Pad no.	Pad Name	X-pos	Y-pos
2	NC VSS	-3315 -3084.77	-377.5 -362.5
3	COM49	-3044.77	-362.5
4	COM50	-3004.77	-362.5
5	COM51	-2964.77	-362.5
7	COM52 COM53	-2924.77 -2884.77	-362.5 -362.5
- 8	COM54	-2844.77	-362.5
9	COM55	-2804.77	-362.5
10	COM56	-2764.77	-362.5
11	COM57	-2724.77	-362.5
13	COM58 COM59	-2684.77 -2644.77	-362.5 -362.5
14	COM60	-2604.77	-362.5
15	COM61	-2564.77	-362.5
16	COM62	-2524.77 -2484.77	-362.5
17 18	COM63 VCOMH	-2484.77	-362.5 -362.5
19	NC	-2334.965	-352.83
20	C2P	-2278.265	-352.83
21	C2P	-2218.265	-352.83
22	C2N C2N	-2136.715 -2055.465	-352.83 -352.83
23	C2N C1P	-2055.465	-352.83
25	C1P	-1904.115	-352.83
26	CIN	-1844.115	-352.83
27	CIN	-1762.865	-352.83
28	VBAT VBAT	-1679.31 -1619.31	-352.83 -352.83
30	VBREF	-1537.51	-352.83
31	BGGND	-1477.51	-352.83
32	VCC	-1416.01	-352.83
33	VCC VCOMH	-1356.01 -1266.955	-352.83 -352.83
35	VCOMH	-1206.955	-352.83
36	VLSS	-1125.155	-352.83
37	VLSS	-1043.355	-352.83
38	VLSS	-983.355	-352.83
39 40	VSS VSS	-920 -856	-352.83 -352.83
41	VSS	-796	-352.83
42	VDD	-732.645	-352.83
43	VDD	-672.645	-352.83
44	BS0 VSS	-595.655 -531.955	-352.83 -352.83
46	BS1	-467.655	-352.83
47	VDD	-403.155	-352.83
48	VDD	-342.555	-352.83
49 50	BS2 VSS	-279.705 -215.705	-352.83 -352.83
51	FR	-151.955	-352.83
52	CL	-89.815	-352.83
53	VSS	-25.665	-352.83
54 55	CS#	38.635	-352.83
56	RES# D/C#	109.835 182.425	-352.83 -352.83
57	VSS	246.125	-352.83
58	R/W#	310.425	-352.83
59	E	373.125	-352.83
60	VDD VDD	457.175 517.175	-352.83 -352.83
62	D0	609.275	-352.83
63	D1	692.475	-352.83
64	D2	765.675	-352.83
65	D3 VSS	828.875 890.325	-352.83 -352.83
67	V85 D4	951.275	-352.83
68	D5	1013.315	-352.83
69	D6	1075.355	-352.83
70	D7	1137.395	-352.83
71 72	VSS VSS	1220.735 1280.735	-352.83 -352.83
73	CLS	1362.585	-352.83
	VDD	1425.285	-352.83
74	VADD	1485.885	-352.83
75	VDD		256.05
75 76	VDD	1553.185	-352.83
75 76 77	VDD VDD	1553.185 1613.185	-352.83
75 76	VDD	1553.185	

	Table 5-1	: SSD13	806Z B
Pad no.	Pad Name	X-pos	Y-pos
81	VCOMH	1875.585	-352.83
82	VCC	1967.185	-352.83
83	VCC	2027.185	-352.83 -352.83
84 85	VLSS VLSS	2109.185 2169.185	-352.83
86	VLSS	2254.185	-352.83
87	NC	2314.185	-352.83
88	NC	2374.185	-352.83
89	VSS	2444.77	-362.5
90	COM31	2484.77	-362.5
91	COM30	2524.77	-362.5
92	COM29	2564.77	-362.5
93	COM28	2604.77	-362.5
94	COM27	2644.77	-362.5
95	COM26	2684.77	-362.5
96 97	COM25	2724.77	-362.5
98	COM24 COM23	2764.77 2804.77	-362.5 -362.5
98	COM23	2844.77	
100	COM22 COM21	2884.77	-362.5 -362.5
101	COM20	2924.77	-362.5
102	COM19	2964.77	-362.5
103	COM19	3004.77	-362.5
104	COM17	3044.77	-362.5
105	VSS	3084.77	-362.5
106	NC	3315	-377.5
107	COM16	3315	-325
108	COM15	3315	-285
109	COM14	3315	-245
110	COM13	3315	-205
111	COM 12	3315	-165
112	COM11	3315	-125
113	COM10	3315	-85
114	COM9	3315	-45 -5
115 116	COM8 COM7	3315 3315	35
117	COM7	3315	75
118	COM5	3315	115
119	COM4	3315	155
120	COM3	3315	195
121	COM2	3315	235
122	COM1	3315	275
123	COM0	3315	315
124	NC	3315	367.5
125	NC	3055.5	356
126	SEG0	3009.5	356
127	SEG1	2962.5	356
128 129	SEG2	2915.5	356
130	SEG3 SEG4	2868.5 2821.5	356 356
131	SEG5	2774.5	356
132	SEG6	2727.5	356
133	SEG7	2680.5	356
134	SEG8	2633.5	356
135	SEG9	2586.5	356
136	SEG10	2539.5	356
137	SEG11	2492.5	356
138	SEG12	2445.5	356
139	SEG13	2398.5	356
140	SEG14	2351.5	356
141	SEG15	2304.5	356
142	SEG16	2257.5	356
143	SEG17	2210.5	356
144	SEG18	2163.5	356
145 146	SEG19 SEG20	2116.5	356 356
146	SEG20 SEG21	2069.5 2022.5	356
148	SEG21	1975.5	356
149	SEG23	1928.5	356
150	SEG24	1881.5	356
151	SEG25	1834.5	356
152	SEG26	1787.5	356
153	SEG27	1740.5	356
154	SEG28	1693.5	356
155	SEG29	1646.5	356
156	SEG30	1599.5	356
150			256
157	SEG31	1552.5	356
157 158	SEG32	1505.5	356
157			

Pad no.	Pad Name	X-pos	Y-pos
161 162	SEG35 SEG36	1364.5 1317.5	356 356
163	SEG37	1270.5	356
164	SEG38	1223.5	356
165	SEG39	1176.5	356
166	SEG40	1129.5	356
167	SEG41	1082.5	356
168	SEG42	1035.5	356
169 170	SEG43 SEG44	988.5 941.5	356 356
171	SEG45	894.5	356
172	SEG46	847.5	356
173	SEG47	800.5	356
174	SEG48	753.5	356
175	SEG49	706.5	356
176	SEG50	659.5	356 356
177 178	SEG51 SEG52	612.5 565.5	356
179	SEG53	518.5	356
180	SEG54	471.5	356
181	SEG55	424.5	356
182	SEG56	377.5	356
183	SEG57	330.5	356
184	SEG58	283.5	356
185	SEG59	236.5	356
186 187	SEG60 SEG61	189.5 142.5	356 356
188	SEG62	95.5	356
189	SEG63	48.5	356
190	SEG64	1.5	356
191	SEG65	-45.5	356
192	SEG66	-92.5	356
193	SEG67	-139.5	356
194 195	SEG68 SEG69	-186.5	356 356
195	SEG70	-233.5 -280.5	356
197	SEG70	-327.5	356
198	SEG72	-374.5	356
199	SEG73	-421.5	356
200	SEG74	-468.5	356
201	SEG75	-515.5	356
202	SEG76	-562.5	356
203	SEG77 SEG78	-609.5 -656.5	356 356
205	SEG79	-703.5	356
206	SEG80	-750.5	356
207	SEG81	-797.5	356
208	SEG82	-844.5	356
209	SEG83	-891.5	356
210	NC CEGO4	-940	356
211	SEG84 SEG85	-988.5	356
212	SEG85 SEG86	-1035.5 -1082.5	356 356
214	SEG87	-1129.5	356
215	SEG88	-1176.5	356
216	SEG89	-1223.5	356
217	SEG90	-1270.5	356
218	SEG91	-1317.5	356
219	SEG92	-1364.5	356
220 221	SEG93 SEG94	-1411.5 -1458.5	356 356
222	SEG94 SEG95	-1438.5	356
223	SEG96	-1552.5	356
224	SEG97	-1599.5	356
225	SEG98	-1646.5	356
226	SEG99	-1693.5	356
227	SEG100	-1740.5	356
228 229	SEG101	-1787.5 -1834.5	356 356
230	SEG102 SEG103	-1834.5	356
231	SEG103 SEG104	-1928.5	356
232	SEG105	-1975.5	356
233	SEG106	-2022.5	356
234	SEG107	-2069.5	356
235	SEG108	-2116.5	356
236	SEG109	-2163.5	356
237	SEG110	-2210.5 -2257.5	356 356
238	SEG111 SEG112	-2304.5	356
240	SEG112 SEG113	-2351.5	356

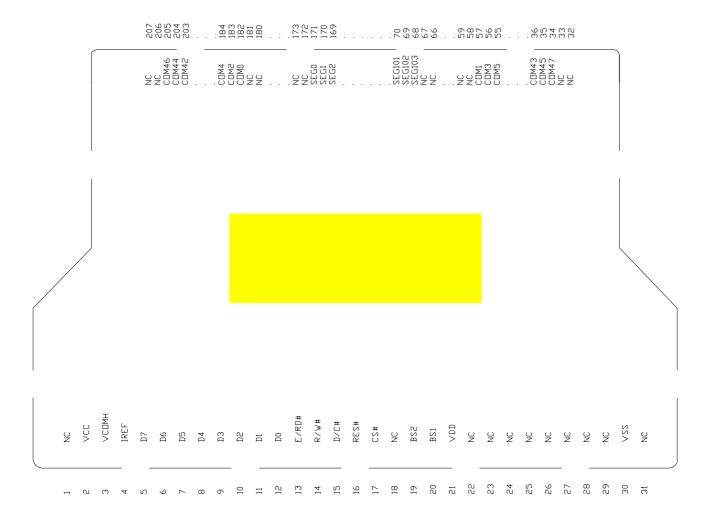
Pad no.	Pad Name	X-pos	Y-pos
241	SEG114	-2398.5	356
242	SEG115	-2445.5	356
243	SEG116	-2492.5	356
244	SEG117	-2539.5	356
245	SEG118	-2586.5	356
246	SEG119	-2633.5	356
247	SEG120	-2680.5	356
248	SEG121	-2727.5	356
249	SEG122	-2774.5	356
250	SEG123	-2821.5	356
251	SEG124	-2868.5	356
252	SEG125	-2915.5	356
253	SEG126	-2962.5	356
254	SEG127	-3009.5	356
255	NC	-3056.5	356
256	NC	-3315	367.5
257	COM32	-3315	315
258	COM33	-3315	275
259	COM34	-3315	235
260	COM35	-3315	195
261	COM36	-3315	155
262	COM37	-3315	115
263	COM38	-3315	75
264	COM39	-3315	35
265	COM40	-3315	-5
266	COM41	-3315	-45
267	COM42	-3315	-85
268	COM43	-3315	-125
269	COM44	-3315	-165
270	COM45	-3315	-205
271	COM46	-3315	-245
272	COM47	-3315	-285
273	COM48	-3315	-325
Pad no.	Pad Name	X-pos	Y-pos
Pin#	Pin name	X-dir	Y-dir
274	TR0	2757.05	114.8
275	TR1	2697.05	114.8
276	TR2	2637.05	114.8
277	TR3	2577.05	114.8
278	VSS	2517.05	114.8
279	TR4	2457.05	114.8
280	TR5	2397.05	114.8
281	TR6	2337.05	114.8

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PIN ARRANGEMENT

6.1 SSD1306TR1 pin assignment

Figure 6-1: SSD1306TR1 Pin Assignment



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Note: (1) COM sequence (Split) is under command setting: DAh, 12h

Table 6-1: SSD1306TR1 Pin Assignment Table

	Table 6-					
Pin no.	Pin Name					
1	NC					
2	VCC					
3	VCOMH					
4	IREF					
5	D7					
6	D6					
7	D5					
8	D4					
9	D3 D2					
10 11	D2					
12	D0					
13	E/RD#					
14	R/W#					
15	D/C#					
16	RES#					
17	CS#					
18	NC					
19	BS2					
20	BS1					
21	VDD					
22	NC					
23	NC					
24	NC					
25	NC NC					
26 27	NC NC					
28	NC NC					
29	NC NC					
30	VSS					
31	NC					
32	NC					
33	NC					
34	COM47					
35	COM45					
36	COM43					
37	COM41					
38	COM39					
39	COM37					
40	COM35					
41	COM33					
42	COM31					
43	COM29					
44	COM27					
45	COM25					
46	COM23					
47	COM21					
48	COM19					
49	COM17					
50 51	COM15 COM13					
52						
53	COM11 COM9					
54	COM7					
55	COM5					
56	COM3					
57	COM1					
58	NC					
59	NC					
60	NC					
61	NC					
62	NC					
63	NC					
64	NC					
65	NC					
66	NC NC					
67	NC 0F0100					
68	SEG103					
69	SEG102					
70	SEG101					
71	SEG100					
72 73	SEG99					
73	SEG98 SEG97					
74 75	SEG97 SEG96					
75 76	SEG95					
76	SEG95 SEG94					
78	SEG93					
79	SEG92					
80	SEG91					

: SSD1306T	R1 Pin Assig
Pin no.	Pin Name
81	SEG90
82	SEG89
83	SEG88
84	SEG87
85	SEG86
86	SEG85
87	SEG84
88	SEG83
89	SEG82
90	SEG81
91	SEG80
92	SEG79
93	SEG78
94	SEG77
95	SEG76
96	SEG75
97	SEG74
98	SEG73
99	SEG72
100	SEG71
101	SEG70
102	SEG70 SEG69
102	SEG68
103	SEG68 SEG67
105	SEG66 SEG65
106	
107 108	SEG64 SEG63
109	SEG62
110	SEG61
111	SEG60
112	SEG59
113	SEG58
114	SEG57
115	SEG56
116	SEG55
117	SEG54
118	SEG53
119	SEG52
120	SEG51
121	SEG50
122	SEG49
123	SEG48
124	SEG47
125	SEG46
126	SEG45
127	SEG44
128	SEG43
129	SEG42
130	SEG41
131	SEG40
132	SEG39
133	SEG38
134	SEG37
135	SEG36
136	SEG35
137	SEG34
138	SEG33
139	SEG32
140	SEG31
141	SEG30
141	SEG29
143	SEG29 SEG28
143	SEG28 SEG27
145	SEG27
146 147	SEG25
	SEG24
148	SEG23
149	SEG22
150	SEG21
151	SEG20
152	SEG19
153	SEG18
154	SEG17
155	SEG16
156	SEG15
157	SEG14
158	SEG13
159	SEG12
160	SEG11

Pin no.	Pin Name					
161	SEG10					
162	SEG10					
163	SEG8					
	SEG8 SEG7					
164						
165	SEG6					
166	SEG5					
167	SEG4					
168	SEG3					
169	SEG2					
170	SEG1					
171	SEG0					
172	NC					
173	NC					
174	NC					
175	NC					
176	NC					
177	NC NC					
178	NC					
179	NC NC					
180	NC NC					
181	NC					
182	COMO					
183						
184	COM2 COM4					
185	COM6					
186	COM8					
187	COM10					
188	COM12					
189	COM14					
190	COM16					
191	COM18					
192	COM20					
193	COM22					
194	COM24					
195	COM26					
196	COM28					
197	COM30					
198	COM32					
199	COM34					
200	COM36					
201	COM38					
202	COM40					
203	COM42					
204	COM44					
205	COM46					
206	NC					
207	NC NC					
207	I NC I					

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7 PIN DESCRIPTION

Key:

I = Input	NC = Not Connected
O =Output	Pull LOW= connect to Ground
I/O = Bi-directional (input/output)	Pull HIGH= connect to V _{DD}
P = Power pin	

Figure 7-1 Pin Description

Pin Name	Type	Description
V_{DD}	P	Power supply pin for core logic operation.
V _{CC}	P	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.
V _{SS}	P	This is a ground pin.
V _{LSS}	P	This is an analog ground pin. It should be connected to V_{SS} externally.
V _{COMH}	О	The pin for COM signal deselected voltage level. A capacitor should be connected between this pin and $V_{\rm SS}$.
V_{BAT}	P	Reserved pin. It should be connected to V _{DD} .
BGGND	P	Reserved pin. It should be connected to ground.
C1P/C1N C2P/C2N	I	Reserved pin. It should be kept NC.
V_{BREF}	P	Reserved pin. It should be kept NC.
BS[2:0]	I	MCU bus interface selection pins. Please refer to Table 7-1 for the details of setting.
I_{REF}	I	This is segment output current reference pin. A resistor should be connected between this pin and V_{SS} to maintain the I_{REF} current at 12.5 uA. Please refer to Figure 8-15 for the details of resistor value.
FR	О	This pin outputs RAM write synchronization signal. Proper timing between MCU data writing and frame display timing can be achieved to prevent tearing effect. It should be kept NC if it is not used. Please refer to Section 8.4 for details usage.
CL	I	This is external clock input pin. When internal clock is enabled (i.e. HIGH in CLS pin), this pin is not used and should be connected to V_{SS} . When internal clock is disabled (i.e. LOW in CLS pin), this pin is the external clock source input pin.
CLS	I	This is internal clock enable pin. When it is pulled HIGH (i.e. connect to $V_{\rm DD}$), internal clock is enabled. When it is pulled LOW, the internal clock is disabled; an external clock source must be connected to the CL pin for normal operation.
RES#	I	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin HIGH (i.e. connect to V_{DD}) during normal operation.
CS#	I	This pin is the chip select input. (active LOW).

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Pin Name	Type	Description
D/C#	I	This is Data/Command control pin. When it is pulled HIGH (i.e. connect to V_{DD}), the data at D[7:0] is treated as data. When it is pulled LOW, the data at D[7:0] will be transferred to the command register. In I ² C mode, this pin acts as SA0 for slave address selection. When 3-wire serial interface is selected, this pin must be connected to V_{SS} . For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams: Figure 13-1 to Figure 13-5 .
E (RD#)	I	When interfacing to a 6800-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH (i.e. connect to V_{DD}) and the chip is selected. When connecting to an 8080-series microprocessor, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I^2C interface is selected, this pin must be connected to V_{SS} .
R/W#(WR#)	I	This is read / write control input pin connecting to the MCU interface. When interfacing to a 6800-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH (i.e. connect to V_{DD}) and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I^2C interface is selected, this pin must be connected to V_{SS} .
D[7:0]	Ю	These are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC. When I²C mode is selected, D2, D1 should be tied together and serve as SDA _{out} , SDA _{in} in application and D0 is the serial clock input, SCL.
TR0-TR6	-	Testing reserved pins. It should be kept NC.
SEG0 ~ SEG127	О	These pins provide Segment switch signals to OLED panel. These pins are V_{SS} state when display is OFF.
COM0 ~ COM63	О	These pins provide Common switch signals to OLED panel. They are in high impedance state when display is OFF.
NC	-	This is dummy pin. Do not group or short NC pins together.

Table 7-1: MCU Bus Interface Pin Selection

SSD1306 Pin Name	I ² C Interface	6800-parallel interface (8 bit)	8080-parallel interface (8 bit)	4-wire Serial interface	3-wire Serial interface
BS0	0	0	0	0	1
BS1	1	0	1	0	0
BS2	0	1	1	0	0

 $\begin{array}{l} \textbf{Note} \\ ^{(1)} \ 0 \ \text{is connected to} \ V_{SS} \\ ^{(2)} \ 1 \ \text{is connected to} \ V_{DD} \end{array}$

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8 FUNCTIONAL BLOCK DESCRIPTIONS

8.1 MCU Interface selection

SSD1306 MCU interface consist of 8 data pins and 5 control pins. The pin assignment at different interface mode is summarized in Table 8-1. Different MCU mode can be set by hardware selection on BS[2:0] pins (please refer to Table 7-1 for BS[2:0] setting).

Table 8-1: MCU interface assignment under different bus interface mode

Pin Name	Pin Name Data/Command Interface									Control Signal				
Bus														
Interface	D7	D6	D5	D4	D3	D2	D1	D 0	E	R/W#	CS#	D/C#	RES#	
8-bit 8080		D[7:0]							RD#	WR#	CS#	D/C#	RES#	
8-bit 6800		D[7:0]							Е	R/W#	CS#	D/C#	RES#	
3-wire SPI	Tie LC)W				NC	SDIN	SCLK	Tie LO'	W	CS#	Tie LOW	RES#	
4-wire SPI	Tie LOW					NC	SDIN	SCLK	Tie LO'	W	CS#	D/C#	RES#	
I^2C	Tie LC)W				SDA _{OUT}	SDA_{IN}	SCL	Tie LO	W		SA0	RES#	

8.1.1 MCU Parallel 6800-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), R/W#, D/C#, E and CS#.

A LOW in R/W# indicates WRITE operation and HIGH in R/W# indicates READ operation. A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write. The E input serves as data latch signal while CS# is LOW. Data is latched at the falling edge of E signal.

Table 8-2: Control pins of 6800 interface

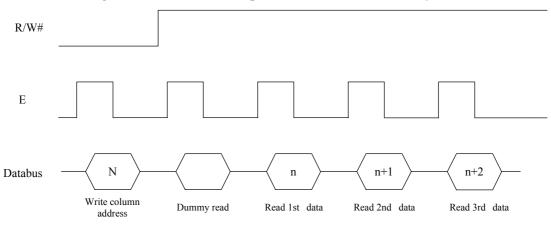
Function	E	R/W#	CS#	D/C#
Write command	↓	L	L	L
Read status	↓	Н	L	L
Write data	↓	L	L	Н
Read data	\downarrow	Н	L	Н

Note

(1) ↓ stands for falling edge of signal H stands for HIGH in signal L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 8-1.

Figure 8-1: Data read back procedure - insertion of dummy read



8.1.2 MCU Parallel 8080-series Interface

The parallel interface consists of 8 bi-directional data pins (D[7:0]), RD#, WR#, D/C# and CS#.

A LOW in D/C# indicates COMMAND read/write and HIGH in D/C# indicates DATA read/write. A rising edge of RD# input serves as a data READ latch signal while CS# is kept LOW. A rising edge of WR# input serves as a data/command WRITE latch signal while CS# is kept LOW.

Figure 8-2: Example of Write procedure in 8080 parallel interface mode

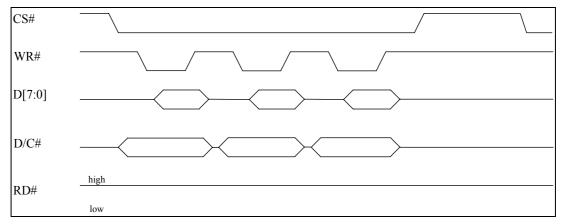
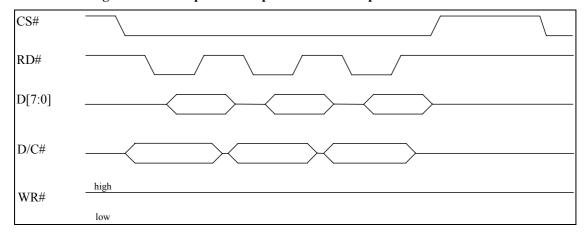


Figure 8-3: Example of Read procedure in 8080 parallel interface mode



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Table 8-3: Control pins of 8080 interface

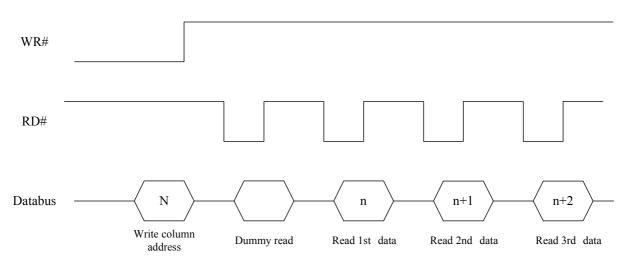
Function	RD#	WR#	CS#	D/C#
Write command	Н	↑	L	L
Read status	1	Н	L	L
Write data	Н	↑	L	Н
Read data	1	Н	L	Н

Note

- (1) ↑ stands for rising edge of signal
- (2) H stands for HIGH in signal
- (3) L stands for LOW in signal

In order to match the operating frequency of display RAM with that of the microprocessor, some pipeline processing is internally performed which requires the insertion of a dummy read before the first actual display data read. This is shown in Figure 8-4.

Figure 8-4: Display data read back procedure - insertion of dummy read



8.1.3 MCU Serial Interface (4-wire SPI)

The 4-wire serial interface consists of serial clock: SCLK, serial data: SDIN, D/C#, CS#. In 4-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, E and R/W# (WR#)# can be connected to an external ground.

Table 8-4: Control pins of 4-wire Serial interface

Function	E(RD#)	R/W#(WR#)	CS#	D/C#	D0
Write command	Tie LOW	Tie LOW	L	L	↑
Write data	Tie LOW	Tie LOW	L	Н	↑

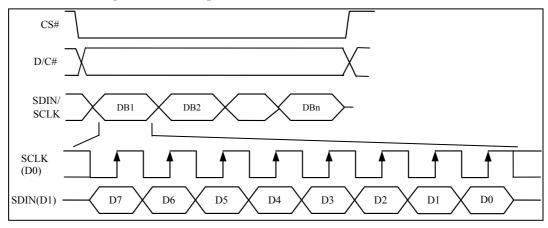
Note

- (1) H stands for HIGH in signal
- (2) L stands for LOW in signal

SDIN is shifted into an 8-bit shift register on every rising edge of SCLK in the order of D7, D6, ... D0. D/C# is sampled on every eighth clock and the data byte in the shift register is written to the Graphic Display Data RAM (GDDRAM) or command register in the same clock.

Under serial mode, only write operations are allowed.

Figure 8-5: Write procedure in 4-wire Serial interface mode



8.1.4 MCU Serial Interface (3-wire SPI)

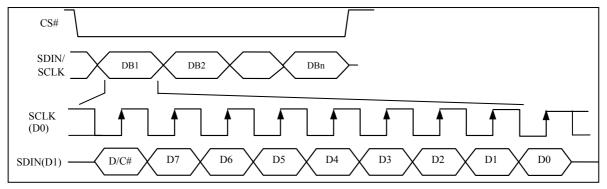
The 3-wire serial interface consists of serial clock SCLK, serial data SDIN and CS#. In 3-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN. For the unused data pins, D2 should be left open. The pins from D3 to D7, R/W# (WR#)#, E and D/C# can be connected to an external ground.

The operation is similar to 4-wire serial interface while D/C# pin is not used. There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence: D/C# bit, D7 to D0 bit. The D/C# bit (first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0). Under serial mode, only write operations are allowed.

Table 8-5: Control pins of 3-wire Serial interface

Function	E(RD#)	R/W #(WR #)	CS#	D/C#	D 0	
Write command	Tie LOW	Tie LOW	L	Tie LOW	1	Note
Write data	Tie LOW	Tie LOW	L	Tie LOW	1	(1) L stands for LOW in signal

Figure 8-6: Write procedure in 3-wire Serial interface mode



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8.1.5 MCU I²C Interface

The I^2C communication interface consists of slave address bit SA0, I^2C -bus data signal SDA (SDA_{OUT}/D₂ for output and SDA_{IN}/D₁ for input) and I^2C -bus clock signal SCL (D₀). Both the data and clock signals must be connected to pull-up resistors. RES# is used for the initialization of device.

a) Slave address bit (SA0)

SSD1306 has to recognize the slave address before transmitting or receiving any information by the I^2C -bus. The device will respond to the slave address following by the slave address bit ("SA0" bit) and the read/write select bit ("R/W#" bit) with the following byte format,

 $b_7 b_6 b_5 b_4 b_3 b_2 b_1 b_0$

0 1 1 1 1 0 SA0 R/W#

"SA0" bit provides an extension bit for the slave address. Either "0111100" or "0111101", can be selected as the slave address of SSD1306. D/C# pin acts as SA0 for slave address selection.

"R/W#" bit is used to determine the operation mode of the I^2C -bus interface. R/W#=1, it is in read mode. R/W#=0, it is in write mode.

b) I²C-bus data signal (SDA)

SDA acts as a communication channel between the transmitter and the receiver. The data and the acknowledgement are sent through the SDA.

It should be noticed that the ITO track resistance and the pulled-up resistance at "SDA" pin becomes a voltage potential divider. As a result, the acknowledgement would not be possible to attain a valid logic 0 level in "SDA".

"SDA_{IN}" and "SDA_{OUT}" are tied together and serve as SDA. The "SDA_{IN}" pin must be connected to act as SDA. The "SDA_{OUT}" pin may be disconnected. When "SDA_{OUT}" pin is disconnected, the acknowledgement signal will be ignored in the I^2 C-bus.

c) I²C-bus clock signal (SCL)

The transmission of information in the I²C-bus is following a clock signal, SCL. Each transmission of data bit is taken place during a single clock period of SCL.

8.1.5.1 I^2 C-bus Write data

The I²C-bus interface gives access to write data and command into the device. Please refer to Figure 8-7 for the write mode of I²C-bus in chronological order.

Note: Co - Continuation bit D/C# - Data / Command Selection bit ACK - Acknowledgement SA0 - Slave address bit R/W# - Read / Write Selection bit $S-Start\ Condition\ /\ P-Stop\ Condition$ Write mode Slave Address 1 byte $n \ge 0$ bytes m > 0 words MSBLSB $\mathsf{I} \mathsf{I} \mathsf{I}$ SSD1306 Slave Address Control byte

Figure 8-7: I²C-bus data format

8.1.5.2 Write mode for I^2C

- 1) The master device initiates the data communication by a start condition. The definition of the start condition is shown in Figure 8-8. The start condition is established by pulling the SDA from HIGH to LOW while the SCL stays HIGH.
- 2) The slave address is following the start condition for recognition use. For the SSD1306, the slave address is either "b0111100" or "b0111101" by changing the SA0 to LOW or HIGH (D/C pin acts as SA0)
- 3) The write mode is established by setting the R/W# bit to logic "0".
- 4) An acknowledgement signal will be generated after receiving one byte of data, including the slave address and the R/W# bit. Please refer to the Figure 8-9 for the graphical representation of the acknowledge signal. The acknowledge bit is defined as the SDA line is pulled down during the HIGH period of the acknowledgement related clock pulse.
- 5) After the transmission of the slave address, either the control byte or the data byte may be sent across the SDA. A control byte mainly consists of Co and D/C# bits following by six "0" 's.
 - a. If the Co bit is set as logic "0", the transmission of the following information will contain data bytes only.
 - b. The D/C# bit determines the next data byte is acted as a command or a data. If the D/C# bit is set to logic "0", it defines the following data byte as a command. If the D/C# bit is set to logic "1", it defines the following data byte as a data which will be stored at the GDDRAM. The GDDRAM column address pointer will be increased by one automatically after each data write.
- 6) Acknowledge bit will be generated after receiving each control byte or data byte.
- 7) The write mode will be finished when a stop condition is applied. The stop condition is also defined in Figure 8-8. The stop condition is established by pulling the "SDA in" from LOW to HIGH while the "SCL" stays HIGH.

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Figure 8-8: Definition of the Start and Stop Condition

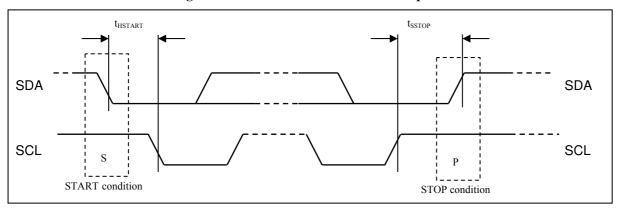
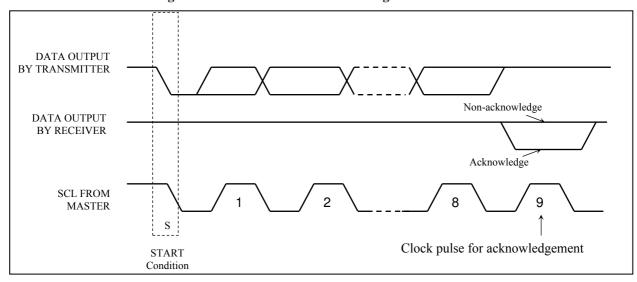


Figure 8-9: Definition of the acknowledgement condition



Please be noted that the transmission of the data bit has some limitations.

Data line is

stable

- 1. The data bit, which is transmitted during each SCL pulse, must keep at a stable state within the "HIGH" period of the clock pulse. Please refer to the Figure 8-10 for graphical representations. Except in start or stop conditions, the data line can be switched only when the SCL is LOW.
- 2. Both the data line (SDA) and the clock line (SCL) should be pulled up by external resistors.

SDA SCL

Change of data

Figure 8-10: Definition of the data transfer condition

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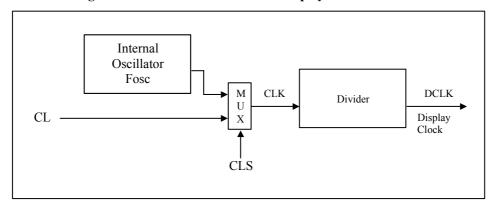
8.2 Command Decoder

This module determines whether the input data is interpreted as data or command. Data is interpreted based upon the input of the D/C# pin.

If D/C# pin is HIGH, D[7:0] is interpreted as display data written to Graphic Display Data RAM (GDDRAM). If it is LOW, the input at D[7:0] is interpreted as a command. Then data input will be decoded and written to the corresponding command register.

8.3 Oscillator Circuit and Display Time Generator

Figure 8-11: Oscillator Circuit and Display Time Generator



This module is an on-chip LOW power RC oscillator circuitry. The operation clock (CLK) can be generated either from internal oscillator or external source CL pin. This selection is done by CLS pin. If CLS pin is pulled HIGH, internal oscillator is chosen and CL should be left open. Pulling CLS pin LOW disables internal oscillator and external clock must be connected to CL pins for proper operation. When the internal oscillator is selected, its output frequency Fosc can be changed by command D5h A[7:4].

The display clock (DCLK) for the Display Timing Generator is derived from CLK. The division factor "D" can be programmed from 1 to 16 by command D5h

$$DCLK = F_{OSC} / D$$

The frame frequency of display is determined by the following formula.

$$F_{FRM} = \frac{F_{osc}}{D \times K \times No. \text{ of Mux}}$$

where

- D stands for clock divide ratio. It is set by command D5h A[3:0]. The divide ratio has the range from 1 to
- K is the number of display clocks per row. The value is derived by

K = Phase 1 period + Phase 2 period + BANK0 pulse width

= 2 + 2 + 50 = 54 at power on reset

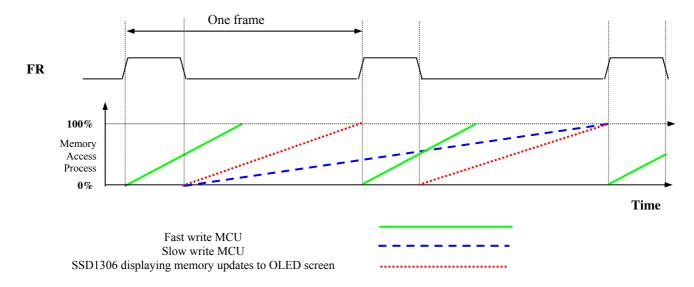
(Please refer to Section 8.6 "Segment Drivers / Common Drivers" for the details of the "Phase")

- Number of multiplex ratio is set by command A8h. The power on reset value is 63 (i.e. 64MUX).
- F_{OSC} is the oscillator frequency. It can be changed by command D5h A[7:4]. The higher the register setting results in higher frequency.

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8.4 FR synchronization

FR synchronization signal can be used to prevent tearing effect.



The starting time to write a new image to OLED driver is depended on the MCU writing speed. If MCU can finish writing a frame image within one frame period, it is classified as fast write MCU. For MCU needs longer writing time to complete (more than one frame but within two frames), it is a slow write one.

For fast write MCU: MCU should start to write new frame of ram data just after rising edge of FR pulse and should be finished well before the rising edge of the next FR pulse.

For slow write MCU: MCU should start to write new frame ram data after the falling edge of the 1st FR pulse and must be finished before the rising edge of the 3rd FR pulse.

8.5 Reset Circuit

When RES# input is LOW, the chip is initialized with the following status:

- 1. Display is OFF
- 2. 128 x 64 Display Mode
- 3. Normal segment and display data column address and row address mapping (SEG0 mapped to address 00h and COM0 mapped to address 00h)
- 4. Shift register data clear in serial interface
- 5. Display start line is set at display RAM address 0
- 6. Column address counter is set at 0
- 7. Normal scan direction of the COM outputs
- 8. Contrast control register is set at 7Fh
- 9. Normal display mode (Equivalent to A4h command)

8.6 Segment Drivers / Common Drivers

Segment drivers deliver 128 current sources to drive the OLED panel. The driving current can be adjusted from 0 to 100uA with 256 steps. Common drivers generate voltage-scanning pulses.

The segment driving waveform is divided into three phases:

- 1. In phase 1, the OLED pixel charges of previous image are discharged in order to prepare for next image content display.
- 2. In phase 2, the OLED pixel is driven to the targeted voltage. The pixel is driven to attain the corresponding voltage level from V_{SS} . The period of phase 2 can be programmed in length from 1 to 15 DCLKs. If the capacitance value of the pixel of OLED panel is larger, a longer period is required to charge up the capacitor to reach the desired voltage.
- 3. In phase 3, the OLED driver switches to use current source to drive the OLED pixels and this is the current drive stage.

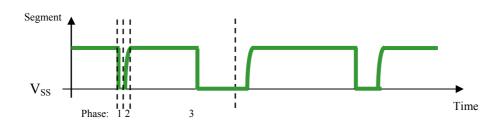


Figure 8-12 : Segment Output Waveform in three phases

After finishing phase 3, the driver IC will go back to phase 1 to display the next row image data. This three-step cycle is run continuously to refresh image display on OLED panel.

In phase 3, if the length of current drive pulse width is set to 50, after finishing 50 DCLKs in current drive phase, the driver IC will go back to phase 1 for next row display.

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8.7 Graphic Display Data RAM (GDDRAM)

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 128 x 64 bits and the RAM is divided into eight pages, from PAGE0 to PAGE7, which are used for monochrome 128x64 dot matrix display, as shown in Figure 8-13.

Row re-mapping PAGE0 (COM0-COM7) PAGE0 (COM 63-COM56) Page 0 PAGE1 (COM8-COM15) PAGE1 (COM 55-COM48) Page 1 PAGE2 (COM47-COM40) PAGE2 (COM16-COM23) Page 2 PAGE3 (COM24-COM31) PAGE3 (COM39-COM32) Page 3 PAGE4 (COM32-COM39) PAGE4 (COM31-COM24) Page 4 PAGE5 (COM40-COM47) PAGE5 (COM23-COM16) Page 5 PAGE6 (COM48-COM55) PAGE6 (COM15-COM8) Page 6 PAGE7 (COM56-COM63) PAGE7 (COM 7-COM0) Page 7 SEG0 -----SEG127 Column re-mapping

Figure 8-13: GDDRAM pages structure of SSD1306

When one data byte is written into GDDRAM, all the rows image data of the same page of the current column are filled (i.e. the whole column (8 bits) pointed by the column address pointer is filled.). Data bit D0 is written into the top row, while data bit D7 is written into bottom row as shown in Figure 8-14.

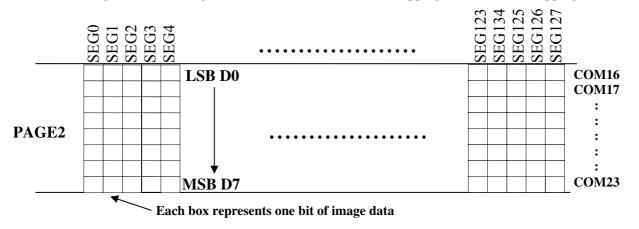


Figure 8-14: Enlargement of GDDRAM (No row re-mapping and column-remapping)

For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software as shown in Figure 8-13.

For vertical shifting of the display, an internal register storing the display start line can be set to control the portion of the RAM data to be mapped to the display (command D3h).

8.8 SEG/COM Driving block

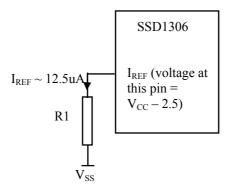
This block is used to derive the incoming power sources into the different levels of internal use voltage and current.

- V_{CC} is the most positive voltage supply.
- V_{COMH} is the Common deselected level. It is internally regulated.
- V_{LSS} is the ground path of the analog and panel current.
- I_{REF} is a reference current source for segment current drivers I_{SEG}. The relationship between reference current and segment current of a color is:

```
I_{SEG} = Contrast / 256 \ x \ I_{REF} \ x \ scale \ factor in which the contrast (0~255) is set by Set Contrast command 81h; and the scale factor is 8 by default.
```

The magnitude of I_{REF} is controlled by the value of resistor, which is connected between I_{REF} pin and V_{SS} as shown in Figure 8-15. It is recommended to set I_{REF} to $12.5 \pm 2uA$ so as to achieve $I_{SEG} = 100uA$ at maximum contrast 255.

Figure 8-15: I_{REF} Current Setting by Resistor Value



Since the voltage at I_{REF} pin is $V_{CC} - 2.5V$, the value of resistor R1 can be found as below:

R1 = (Voltage at $I_{REF} - V_{SS}$) / I_{REF} = (12 - 2.5) / 12.5uA = 760KΩ

For $I_{REF} = 12.5uA$, $V_{CC} = 12V$:

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8.9 Power ON and OFF sequence

The following figures illustrate the recommended power ON and power OFF sequence of SSD1306

Power ON sequence:

- 1. Power ON V_{DD}
- 2. After V_{DD} become stable, set RES# pin LOW (logic low) for at least 3us (t₁) ⁽⁴⁾ and then HIGH (logic high).
- 3. After set RES# pin LOW (logic low), wait for at least 3us (t_2). Then Power ON V_{CC} .
- 4. After V_{CC} become stable, send command AFh for display ON. SEG/COM will be ON after 100ms (t_{AF}).

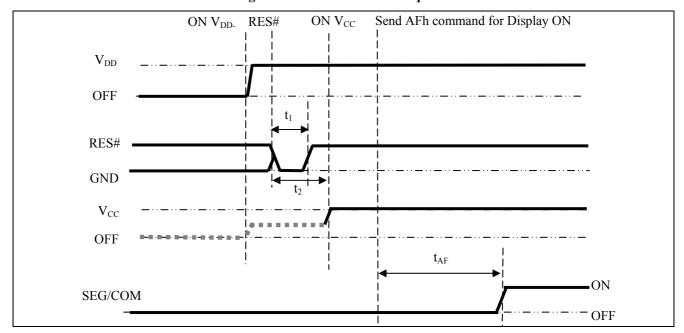


Figure 8-16: The Power ON sequence

Power OFF sequence:

- 1. Send command AEh for display OFF.
- 2. Power OFF $V_{CC}^{(1),(2),(3)}$
- 3. Power OFF V_{DD} after t_{OFF}. (5) (Typical t_{OFF}=100ms)

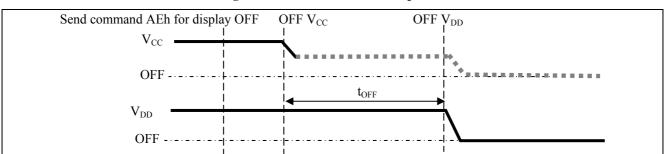


Figure 8-17: The Power OFF sequence

Note:

- ⁽¹⁾ Since an ESD protection circuit is connected between V_{DD} and V_{CC} , V_{CC} becomes lower than V_{DD} whenever V_{DD} is ON and V_{CC} is OFF as shown in the dotted line of V_{CC} in Figure 8-16 and Figure 8-17.
- $^{(2)}V_{CC}$ should be kept float (i.e. disable) when it is OFF.
- $^{(3)}$ Power Pins (V_{DD} , V_{CC}) can never be pulled to ground under any circumstance.
- $^{(4)}$ The register values are reset after t_1 .
- $^{(5)}$ V_{DD} should not be Power OFF before V_{CC} Power OFF.

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9 COMMAND TABLE

Table 9-1: Command Table

(D/C#=0, R/W#(WR#) = 0, E(RD#=1) unless specific setting is stated)

	I. Fundamental Command Table												
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description		
0	81	1	0	0	0	0	0	0	1	Set Contrast Control	Double byte command to select 1 out of 256		
0	A[7:0]	A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		contrast steps. Contrast increases as the value		
											increases.		
											(RESET = 7Fh)		
0	A4/A5	1	0	1	0	0	1	0	X_0	Entire Display ON	A4h, X_0 =0b: Resume to RAM content display		
											(RESET)		
											Output follows RAM content		
											A5h, X_0 =1b: Entire display ON		
											Output ignores RAM content		
0	A6/A7	1	0	1	0	0	1	1	X_0	Set Normal/Inverse	A6h, X[0]=0b: Normal display (RESET)		
										Display	0 in RAM: OFF in display panel		
											1 in RAM: ON in display panel		
											A7h, X[0]=1b: Inverse display		
											0 in RAM: ON in display panel		
0	4.5		_					-	7.7	G . D' 1 ONIOEE	1 in RAM: OFF in display panel		
-	AΕ	1	0	l	0	1	1	1	X_0	Set Display ON/OFF	AEh, X[0]=0b:Display OFF (sleep mode)		
	AF										(RESET)		
											AFh X[0]=1b:Display ON in normal mode		

2.	Scrolling	Com	mand	l Tab	le						
D/	C# Hex	D7	D6	D5	D4	D3	D2	D1	D 0	Command	Description
0	26/27	0	0	1	0	0	1	1	X_0	Continuous	26h, X[0]=0, Right Horizontal Scroll
0	A[7:0]	0	0	0	0	0	0	0	0	Horizontal Scroll	27h, X[0]=1, Left Horizontal Scroll
0	B[2:0]	*	*	*	*	*	B_2	B_1	\mathbf{B}_0	Setup	(Horizontal scroll by 1 column)
0	C[2:0]	*	*	*	*	*	C_2	C_1	C_0		A[7:0]: Dummy byte (Set as 00h)
0	D[2:0]	*	*	*	*	*	D_2	D_1	D_0		B[2:0] : Define start page address
0	E[7:0]	0	0	0	0	0	0	0	0		000b – PAGE0 011b – PAGE3 110b – PAGE6
0	F[7:0]	1	1	1	1	1	1	1	1		001b – PAGE1 100b – PAGE4 111b – PAGE7
	1 [7.0]	1	1	1	1		1 .	1	1		010b – PAGE2 101b – PAGE5
											C[2:0]: Set time interval between each scroll step in
											terms of frame frequency
											000b - 5 frames $100b - 3$ frames
											001b – 64 frames 101b – 4 frames
											010b – 128 frames 110b – 25 frame
											011b – 256 frames 111b – 2 frame
											D[2:0] : Define end page address
											000b - PAGE0 011b - PAGE3 110b - PAGE6
											001b - PAGE1 100b - PAGE4 111b - PAGE7
											010b – PAGE2 101b – PAGE5
											The value of D[2:0] must be larger or equal
											to B[2:0]
											E[7:0] : Dummy byte (Set as 00h)
											[] 5.5 (
											F[7:0]: Dummy byte (Set as FFh)
											, , , , , , , , , , , , , , , , , , , ,

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2. \$	Scrolling (Comi	nand	Tab	le						
D/	C# Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	29/2A	0	0	1	0	1	0	X_1	X_0	Continuous	29h, X ₁ X ₀ =01b : Vertical and Right Horizontal Scroll
0	A[2:0]	0	0	0	0	0	0	0	0	Vertical and	2Ah, $X_1X_0=10b$: Vertical and Left Horizontal Scroll
0	B[2:0]	*	*	*	*	*	B_2	\mathbf{B}_1	B_0	Horizontal Scroll	(Horizontal scroll by 1 column)
0	C[2:0]	*	*	*	*	*	C_2	C_1	C_0	Setup	A[7:0] : Dummy byte
0	D[2:0]	*	*	*	*	*	D_2	D_1	D_0	~ · · · · · · ·	-[]
0		*	*	E_5	E_4		E_2	E_1	E_0		B[2:0] : Define start page address
U	E[5:0]			E 5	E ₄	E_3	E ₂	\mathbf{E}_1	E ₀		000b – PAGE0 011b – PAGE3 110b – PAGE6
											001b – PAGE1 100b – PAGE4 111b – PAGE7
											010b – PAGE2 101b – PAGE5
											0100 - 1 AGE2 1010 - 1 AGE3
											C[2:0] . Cat time internal between each small stem in
											C[2:0] : Set time interval between each scroll step in
											terms of frame frequency
											000b – 5 frames 100b – 3 frames
											001b – 64 frames 101b – 4 frames
											010b – 128 frames 110b – 25 frame
											011b – 256 frames 111b – 2 frame
											D[2:0] : Define end page address
											000b – PAGE0 011b – PAGE3 110b – PAGE6
											001b - PAGE1 100b - PAGE4 111b - PAGE7
											010b – PAGE2 101b – PAGE5
											The value of D[2:0] must be larger or equal
											to B[2:0]
											w 5[2.0]
											E[5:0] : Vertical scrolling offset
											e.g. E[5:0]= 01h refer to offset =1 row
											E[5:0] = 3Fh refer to offset $= 63$ rows
											Note
											(1) No continuous vertical scrolling is available.
											Two continuous vertical scronning is available.
0	2E	0	0	1	0	1	1	1	0	Deactivate scroll	Stop scrolling that is configured by command
				1		1		1		Deactivate seron	26h/27h/29h/2Ah.
											Note
											(1) After sending 2Eh command to deactivate the scrolling
											action, the ram data needs to be rewritten.
											and the second to be remitted.
0	2F	0	0	1	0	1	1	1	1	Activate scroll	Start scrolling that is configured by the scrolling setup
				_		-	1	1	-	1001 (000 501011	commands: 26h/27h/29h/2Ah with the following valid
											sequences:
											poquomeos.
											Valid command sequence 1: 26h : 2Eh
											Valid command sequence 1: 26h; 2Fh.
											Valid command sequence 2: 27h;2Fh.
											Valid command sequence 3: 29h;2Fh.
											Valid command sequence 4: 2Ah;2Fh.
											1 :6((2/1 211 271))
											For example, if "26h; 2Ah; 2Fh." commands are
											issued, the setting in the last scrolling setup command,
											i.e. 2Ah in this case, will be executed. In other words,
											setting in the last scrolling setup command overwrites
											the setting in the previous scrolling setup commands.

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$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	2. Sc	rolling	Com	mand	l Tab	le							
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	D/C#	#Hex	D7	D6	D5	D4	D3	D3	D2	D1	D0	Command Des	escription
$40h\sim7Fh) < B[6:0]$ (4) The last row of the scroll area shifts to the f of the scroll area. (5) For 64d MUX display $A[5:0] = 0, B[6:0] = 64 : \text{ whole area scrolls}$ $A[5:0] = 0, B[6:0] < 64 : \text{ top area scrolls}$ $A[5:0] + B[6:0] < 64 : \text{ central area scrolls}$ $A[5:0] + B[6:0] = 64 : \text{ bottom area scrolls}$		Hex A3 A[5:0]	D7 1 *	D6 0 *	D5 1 A ₅	0 A ₄	0 A ₃	0 A ₃	0 A ₂	1 A ₁	1 A ₀	Set Vertical Scroll A[5] Area B[6] Noi (1) (2) (3a) (3b) (4) (4) (7) (5) (6) (7) (A) (A) (A) (A) (A) (A) (A) (A) (A) (A	5:0]: Set No. of rows in top fixed area. The No. of rows in top fixed area is referenced to the top of the GDDRAM (i.e. row 0).[RESET = 0] 6:0]: Set No. of rows in scroll area. This is the number of rows to be used for vertical scrolling. The scroll area starts in the first row below the top fixed area. [RESET = 64] 6:0] +B[6:0] = MUX ratio 8[6:0] = MUX ratio 9 Vertical scrolling offset (E[5:0] in 29h/2Ah) < B[6:0] 9 Set Display Start Line (X ₅ X ₄ X ₃ X ₂ X ₁ X ₀ of 40h~7Fh) < B[6:0] The last row of the scroll area shifts to the first row of the scroll area. For 64d MUX display 15:0] = 0, B[6:0] = 64: whole area scrolls 15:0] = 0, B[6:0] < 64: top area scrolls 15:0] + B[6:0] < 64: central area scrolls

	ddressi						D2	D1	D0	G 1	h
D/C#		D7			D4		D2	D1	D0	Command	Description
0	00~0F	0	0	0	0	X ₃	X ₂	X ₁	X_0	Set Lower Column Start Address for Page Addressing Mode	Set the lower nibble of the column start address register for Page Addressing Mode using X[3:0] as data bits. The initial display line register is reset to 0000b after RESET.
											Note (1) This command is only for page addressing mode
0	10~1F	0	0	0	1	X ₃	X ₂	X ₁	X_0	Set Higher Column Start Address for Page Addressing Mode	Set the higher nibble of the column start address register for Page Addressing Mode using X[3:0] as data bits. The initial display line register is reset to 0000b after RESET. Note
	20		•								(1) This command is only for page addressing mode
0	20 A[1:0]	0 *	0 *	1 *	0 *	0 *	0 *	$\begin{bmatrix} 0 \\ A_1 \end{bmatrix}$	A_0	Set Memory Addressing Mode	A[1:0] = 00b, Horizontal Addressing Mode A[1:0] = 01b, Vertical Addressing Mode A[1:0] = 10b, Page Addressing Mode (RESET) A[1:0] = 11b, Invalid
0 0 0	21 A[6:0] B[6:0]	0 *	0 A ₆ B ₆	1 A ₅ B ₅	0 A ₄ B ₄	0 A ₃ B ₃	0 A ₂ B ₂	0 A_1 B_1	$egin{array}{c} 1 \\ A_0 \\ B_0 \end{array}$	Set Column Address	Setup column start and end address A[6:0]: Column start address, range: 0-127d, (RESET=0d)
											B[6:0]: Column end address, range : 0-127d, (RESET =127d) Note (1) This command is only for horizontal or vertical addressing mode.

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3. A	3. Addressing Setting Command Table												
D/C	#Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description		
0	22	0	0	1	0	0	0	1	0	Set Page Address	Setup page start and end address		
0	A[2:0]	*	*	*	*	*	A_2	\mathbf{A}_1	A_0		A[2:0] : Page start Address, range : 0-7d,		
0	B[2:0]	*	*	*	*	*	B_2	\mathbf{B}_1	B_0		(RESET = 0d)		
											B[2:0] : Page end Address, range : 0-7d, (RESET = 7d)		
											Note		
											(1) This command is only for horizontal or vertical		
											addressing mode.		
0	B0~B7	1	0	1	1	0	X_2	X_1	X_0	Set Page Start	Set GDDRAM Page Start Address		
							_	•		Address for Page	(PAGE0~PAGE7) for Page Addressing Mode		
										Addressing Mode	using X[2:0].		
											Note		
											(1) This command is only for page addressing mode		

										lated) Command Tab	
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	$\mathbf{D0}$	Command	Description
0	40~7F	0	1	X ₅	X ₄	X ₃	X ₂	X ₁	X_0	Set Display Start Line	eSet display RAM display start line register from 0-63 using $X_5X_3X_2X_1X_0$. Display start line register is reset to 000000b during RESET.
0	A0/A1	1	0	1	0	0	0	0	X_0	Set Segment Re-map	A0h, X[0]=0b: column address 0 is mapped to SEG0 (RESET) A1h, X[0]=1b: column address 127 is mapped to SEG0
0	A8 A[5:0]	1 *	0 *	1 A ₅	0 A ₄	1 A ₃	0 A ₂	0 A ₁	0 A ₀	Set Multiplex Ratio	Set MUX ratio to N+1 MUX N=A[5:0]: from 16MUX to 64MUX, RESET= 111111b (i.e. 63d, 64MUX) A[5:0] from 0 to 14 are invalid entry.
0	C0/C8	1	1	0	0	X ₃	0	0	0	Set COM Output Scan Direction	C0h, X[3]=0b: normal mode (RESET) Scan from COM0 to COM[N-1] C8h, X[3]=1b: remapped mode. Scan from COM[N-1] to COM0 Where N is the Multiplex ratio.
0	D3 A[5:0]	1 *	1 *	0 A ₅	1 A ₄	0 A ₃	0 A ₂	1 A ₁	1 A ₀	Set Display Offset	Set vertical shift by COM from 0d~63d The value is reset to 00h after RESET.
0	DA A[5:4]	1 0	1 0	0 A ₅	1 A ₄	1 0	0 0	1 1	0 0	Set COM Pins Hardware Configuration	A[4]=0b, Sequential COM pin configuration A[4]=1b(RESET), Alternative COM pin configuration A[5]=0b(RESET), Disable COM Left/Right remap A[5]=1b, Enable COM Left/Right remap

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5. Ti	ming &	Drivi	ng Scl	heme	Settin	g Cor	nman	d Tal	ble		
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	D5 A[7:0]	1 A ₇	1 A ₆	0 A ₅	1 A ₄	0 A ₃	1 A ₂	0 A_1	A_0	Set Display Clock Divide Ratio/Oscillator Frequency	A[3:0]: Define the divide ratio (D) of the display clocks (DCLK): Divide ratio= A[3:0] + 1, RESET is 0000b (divide ratio = 1)
											A[7:4]: Set the Oscillator Frequency, F _{OSC} . Oscillator Frequency increases with the value of A[7:4] and vice versa. RESET is 1000b Range:0000b~1111b Frequency increases as setting value increases.
0	D9 A[7:0]	1 A ₇	1 A ₆	0 A ₅	1 A ₄	1 A ₃	0 A ₂	0 A ₁	1 A ₀	Set Pre-charge Period	A[3:0]: Phase 1 period of up to 15 DCLK clocks 0 is invalid entry (RESET=2h)
											A[7:4]: Phase 2 period of up to 15 DCLK clocks 0 is invalid entry (RESET=2h)
0	DB A[6:4]	1 0	1 A ₆	0 A ₅	1 A ₄	1 0	0	1 0	1 0	Set V _{COMH} Deselect Level	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$
0	Е3	1	1	1	0	0	0	1	1	NOP	Command for no operation

Note
(1) "*" stands for "Don't care".

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Table 9-2: Read Command Table

Bit Pattern	Command	Descrip	otion
$D_7D_6D_5D_4D_3D_2D_1D_0$	Status Register Read	D[7]:	Reserved
		D[6]:	"1" for display OFF / "0" for display ON
		D[5]:	Reserved
		D[4] :	Reserved
		D[3] :	Reserved
		D[2]:	Reserved
		D[1] :	Reserved
		D[0]:	Reserved

Note

9.1 Data Read / Write

To read data from the GDDRAM, select HIGH for both the R/W# (WR#) pin and the D/C# pin for 6800-series parallel mode and select LOW for the E (RD#) pin and HIGH for the D/C# pin for 8080-series parallel mode. No data read is provided in serial mode operation.

In normal data read mode the GDDRAM column address pointer will be increased automatically by one after each data read.

Also, a dummy read is required before the first data read.

To write data to the GDDRAM, select LOW for the R/W# (WR#) pin and HIGH for the D/C# pin for both 6800-series parallel mode and 8080-series parallel mode. The serial interface mode is always in write mode. The GDDRAM column address pointer will be increased automatically by one after each data write.

Table 9-3: Address increment table (Automatic)

D/C#	R/W# (WR#)	Comment	Address Increment
0	0	Write Command	No
0	1	Read Status	No
1	0	Write Data	Yes
1	1	Read Data	Yes

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⁽¹⁾ Patterns other than those given in the Command Table are prohibited to enter the chip as a command; as unexpected results can occur.

10 COMMAND DESCRIPTIONS

10.1 Fundamental Command

10.1.1 Set Lower Column Start Address for Page Addressing Mode (00h~0Fh)

This command specifies the lower nibble of the 8-bit column start address for the display data RAM under Page Addressing Mode. The column address will be incremented by each data access. Please refer to Section Table 9-1 and Section 10.1.3 for details.

10.1.2 Set Higher Column Start Address for Page Addressing Mode (10h~1Fh)

This command specifies the higher nibble of the 8-bit column start address for the display data RAM under Page Addressing Mode. The column address will be incremented by each data access. Please refer to Section Table 9-1 and Section 10.1.3 for details.

10.1.3 Set Memory Addressing Mode (20h)

There are 3 different memory addressing mode in SSD1306: page addressing mode, horizontal addressing mode and vertical addressing mode. This command sets the way of memory addressing into one of the above three modes. In there, "COL" means the graphic display data RAM column.

Page addressing mode (A[1:0]=10xb)

In page addressing mode, after the display RAM is read/written, the column address pointer is increased automatically by 1. If the column address pointer reaches column end address, the column address pointer is reset to column start address and page address pointer is not changed. Users have to set the new page and column addresses in order to access the next page RAM content. The sequence of movement of the PAGE and column address point for page addressing mode is shown in Figure 10-1.

 COL0
 COL 1

 COL 126
 COL 127

 PAGE0
 →
 →
 →

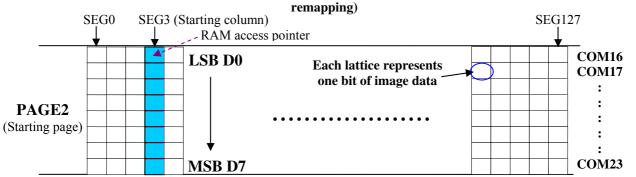
Figure 10-1: Address Pointer Movement of Page addressing mode

In normal display data RAM read or write and page addressing mode, the following steps are required to define the starting RAM access pointer location:

- Set the page start address of the target display location by command B0h to B7h.
- Set the lower start column address of pointer by command 00h~0Fh.
- Set the upper start column address of pointer by command 10h~1Fh.

For example, if the page address is set to B2h, lower column address is 03h and upper column address is 10h, then that means the starting column is SEG3 of PAGE2. The RAM access pointer is located as shown in Figure 10-2. The input data byte will be written into RAM position of column 3.

Figure 10-2 : Example of GDDRAM access pointer setting in Page Addressing Mode (No row and column-



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Horizontal addressing mode (A[1:0]=00b)

In horizontal addressing mode, after the display RAM is read/written, the column address pointer is increased automatically by 1. If the column address pointer reaches column end address, the column address pointer is reset to column start address and page address pointer is increased by 1. The sequence of movement of the page and column address point for horizontal addressing mode is shown in Figure 10-3. When both column and page address pointers reach the end address, the pointers are reset to column start address and page start address (Dotted line in Figure 10-3.)

Figure 10-3: Address Pointer Movement of Horizontal addressing mode

Vertical addressing mode: (A[1:0]=01b)

In vertical addressing mode, after the display RAM is read/written, the page address pointer is increased automatically by 1. If the page address pointer reaches the page end address, the page address pointer is reset to page start address and column address pointer is increased by 1. The sequence of movement of the page and column address point for vertical addressing mode is shown in Figure 10-4. When both column and page address pointers reach the end address, the pointers are reset to column start address and page start address (Dotted line in Figure 10-4.)

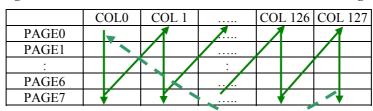


Figure 10-4: Address Pointer Movement of Vertical addressing mode

In normal display data RAM read or write and horizontal / vertical addressing mode, the following steps are required to define the RAM access pointer location:

- Set the column start and end address of the target display location by command 21h.
- Set the page start and end address of the target display location by command 22h.

Example is shown in Figure 10-5.

10.1.4 Set Column Address (21h)

This triple byte command specifies column start address and end address of the display data RAM. This command also sets the column address pointer to column start address. This pointer is used to define the current read/write column address in graphic display data RAM. If horizontal address increment mode is enabled by command 20h, after finishing read/write one column data, it is incremented automatically to the next column address. Whenever the column address pointer finishes accessing the end column address, it is reset back to start column address and the row address is incremented to the next row.

10.1.5 Set Page Address (22h)

This triple byte command specifies page start address and end address of the display data RAM. This command also sets the page address pointer to page start address. This pointer is used to define the current read/write page address in graphic display data RAM. If vertical address increment mode is enabled by command 20h, after finishing read/write one page data, it is incremented automatically to the next page address. Whenever the page address pointer finishes accessing the end page address, it is reset back to start page address.

The figure below shows the way of column and page address pointer movement through the example: column start address is set to 2 and column end address is set to 125, page start address is set to 1 and page end address is set to 6; Horizontal address increment mode is enabled by command 20h. In this case, the graphic display data RAM column accessible range is from column 2 to column 125 and from page 1 to page 6 only. In addition, the column address pointer is set to 2 and page address pointer is set to 1. After finishing read/write one pixel of data, the column address is increased automatically by 1 to access the next RAM location for next read/write operation (*solid line in Figure 10-5*). Whenever the column address pointer finishes accessing the end column 125, it is reset back to column 2 and page address is automatically increased by 1 (*solid line in Figure 10-5*). While the end page 6 and end column 125 RAM location is accessed, the page address is reset back to 1 and the column address is reset back to 2 (*dotted line in Figure 10-5*).

 Col 0
 Col 1
 Col 2

 Col 125
 Col 126
 Col 127

 PAGE0

Figure 10-5: Example of Column and Row Address Pointer Movement

10.1.6 Set Display Start Line (40h~7Fh)

This command sets the Display Start Line register to determine starting address of display RAM, by selecting a value from 0 to 63. With value equal to 0, RAM row 0 is mapped to COM0. With value equal to 1, RAM row 1 is mapped to COM0 and so on.

Refer to Table 10-1 for more illustrations.

10.1.7 Set Contrast Control for BANK0 (81h)

This command sets the Contrast Setting of the display. The chip has 256 contrast steps from 00h to FFh. The segment output current increases as the contrast step value increases.

10.1.8 Set Segment Re-map (A0h/A1h)

This command changes the mapping between the display data column address and the segment driver. It allows flexibility in OLED module design. Please refer to Table 9-1.

This command only affects subsequent data input. Data already stored in GDDRAM will have no changes.

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10.1.9 Entire Display ON (A4h/A5h)

A4h command enable display outputs according to the GDDRAM contents.

If A5h command is issued, then by using A4h command, the display will resume to the GDDRAM contents. In other words, A4h command resumes the display from entire display "ON" stage.

A5h command forces the entire display to be "ON", regardless of the contents of the display data RAM.

10.1.10 Set Normal/Inverse Display (A6h/A7h)

This command sets the display to be either normal or inverse. In normal display a RAM data of 1 indicates an "ON" pixel while in inverse display a RAM data of 0 indicates an "ON" pixel.

10.1.11 Set Multiplex Ratio (A8h)

This command switches the default 63 multiplex mode to any multiplex ratio, ranging from 16 to 63. The output pads COM0~COM63 will be switched to the corresponding COM signal.

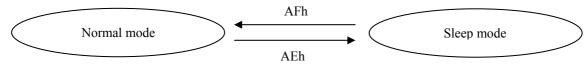
10.1.12 Set Display ON/OFF (AEh/AFh)

These single byte commands are used to turn the OLED panel display ON or OFF.

When the display is ON, the selected circuits by Set Master Configuration command will be turned ON. When the display is OFF, those circuits will be turned OFF and the segment and common output are in V_{SS} state and high impedance state, respectively. These commands set the display to one of the two states:

AEh : Display OFFAFh : Display ON

Figure 10-6: Transition between different modes



10.1.13 Set Page Start Address for Page Addressing Mode (B0h~B7h)

This command positions the page start address from 0 to 7 in GDDRAM under Page Addressing Mode. Please refer to Table 9-1 and Section 10.1.3 for details.

10.1.14 Set COM Output Scan Direction (C0h/C8h)

This command sets the scan direction of the COM output, allowing layout flexibility in the OLED module design. Additionally, the display will show once this command is issued. For example, if this command is sent during normal display then the graphic display will be vertically flipped immediately. Please refer to Table 10-3 for details.

10.1.15 Set Display Offset (D3h)

This is a double byte command. The second command specifies the mapping of the display start line to one of COM0~COM63 (assuming that COM0 is the display start line then the display start line register is equal to 0).

For example, to move the COM16 towards the COM0 direction by 16 lines the 6-bit data in the second byte should be given as 010000b. To move in the opposite direction by 16 lines the 6-bit data should be given by 64 - 16, so the second byte would be 100000b. The following two tables (Table 10-1, Table 10-2) show the example of setting the command C0h/C8h and D3h.

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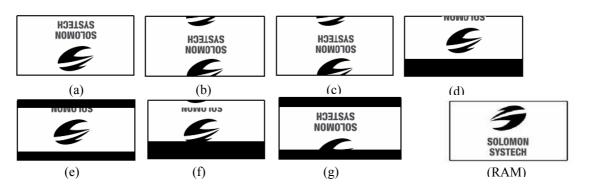
Table 10-1: Example of Set Display Offset and Display Start Line with no Remap

	L						Out							<u> </u>
	-	6 Nor		Nor			mal		mal		mal		mal	Set MUX ratio(A8h) COM Normal / Remapped (C0h / C8h)
Hardwa		()		3	•)	()		8	•	0	Display offset (D3h)
pin nar		Row0	RAM0	Row8	RAM8	Row0	RAM8	Row0	RAM0	Row8	0 RAM8	Row0	RAM8	Display start line (40h - 7Fh)
COM		Row1	RAM1	Row9	RAM9	Row1	RAM9	Row1	RAM1	Row9	RAM9	Row1	RAM9	
COM		Row2 Row3	RAM2 RAM3	Row10 Row11	RAM10 RAM11	Row2 Row3	RAM10 RAM11	Row2 Row3	RAM2 RAM3	Row10 Row11	RAM10 RAM11	Row2 Row3	RAM10 RAM11	
COM	4	Row4	RAM4	Row12	RAM12	Row4	RAM12	Row4	RAM4	Row12	RAM12	Row4	RAM12	
COM		Row5 Row6	RAM5 RAM6	Row13 Row14	RAM13 RAM14	Row5 Row6	RAM13 RAM14	Row5 Row6	RAM5 RAM6	Row13 Row14	RAM13 RAM14	Row5 Row6	RAM13 RAM14	
COM	7	Row7	RAM7	Row15	RAM15	Row7	RAM15	Row7	RAM7	Row15	RAM15	Row7	RAM15	
COM		Row8 Row9	RAM8 RAM9	Row16 Row17	RAM16 RAM17	Row8 Row9	RAM16 RAM17	Row8 Row9	RAM8 RAM9	Row16 Row17	RAM16 RAM17	Row8 Row9	RAM16 RAM17	
COM		Row10	RAM10	Row18	RAM18	Row10	RAM18	Row10	RAM10	Row18	RAM18	Row10	RAM18	
COM		Row11	RAM11 RAM12	Row19	RAM19	Row11	RAM19	Row11	RAM11	Row19	RAM19 RAM20	Row11	RAM19 RAM20	
COM1		Row12 Row13	RAM13	Row20 Row21	RAM20 RAM21	Row12 Row13	RAM20 RAM21	Row12 Row13	RAM12 RAM13	Row20 Row21	RAM21	Row12 Row13	RAM21	
COM1		Row14	RAM14	Row22	RAM22	Row14	RAM22	Row14	RAM14	Row22	RAM22	Row14	RAM22	
COM1		Row15 Row16	RAM15 RAM16	Row23 Row24	RAM23 RAM24	Row15 Row16	RAM23 RAM24	Row15 Row16	RAM15 RAM16	Row23 Row24	RAM23 RAM24	Row15 Row16	RAM23 RAM24	
COM1	17 F	Row17	RAM17	Row25	RAM25	Row17	RAM25	Row17	RAM17	Row25	RAM25	Row17	RAM25	
COM1		Row18 Row19	RAM18 RAM19	Row26 Row27	RAM26 RAM27	Row18 Row19	RAM26 RAM27	Row18 Row19	RAM18 RAM19	Row26 Row27	RAM26 RAM27	Row18 Row19	RAM26 RAM27	
COM2	20 F	Row20	RAM20	Row28	RAM28	Row20	RAM28	Row20	RAM20	Row28	RAM28	Row20	RAM28	
COM2		Row21 Row22	RAM21 RAM22	Row29 Row30	RAM29 RAM30	Row21 Row22	RAM29 RAM30	Row21 Row22	RAM21 RAM22	Row29 Row30	RAM29 RAM30	Row21 Row22	RAM29 RAM30	
COM2		Row23	RAM23	Row31	RAM31	Row23	RAM31	Row23	RAM23	Row31	RAM31	Row23	RAM31	
COM		Row24	RAM24 RAM25	Row32	RAM32	Row25	RAM32	Row24	RAM24	Row32	RAM32	Row24 Row25	RAM32	
COM2		Row25 Row26	RAM25 RAM26	Row33 Row34	RAM33 RAM34	Row25 Row26	RAM33 RAM34	Row25 Row26	RAM25 RAM26	Row33 Row34	RAM33 RAM34	Row25	RAM33 RAM34	
COM2	27 F	Row27	RAM27	Row35	RAM35	Row27	RAM35	Row27	RAM27	Row35	RAM35	Row27	RAM35	
COM2		Row28 Row29	RAM28 RAM29	Row36 Row37	RAM36 RAM37	Row28 Row29	RAM36 RAM37	Row28 Row29	RAM28 RAM29	Row36 Row37	RAM36 RAM37	Row28 Row29	RAM36 RAM37	
COM	30 F	Row30	RAM30	Row38	RAM38	Row30	RAM38	Row30	RAM30	Row38	RAM38	Row30	RAM38	
COMS		Row31 Row32	RAM31 RAM32	Row39 Row40	RAM39 RAM40	Row31 Row32	RAM39 RAM40	Row31 Row32	RAM31 RAM32	Row39 Row40	RAM39 RAM40	Row31 Row32	RAM39 RAM40	
COM		Row33	RAM33	Row41	RAM41	Row33	RAM41	Row33	RAM33	Row41	RAM41	Row33	RAM41	
COM3		Row34 Row35	RAM34 RAM35	Row42 Row43	RAM42 RAM43	Row34 Row35	RAM42 RAM43	Row34 Row35	RAM34 RAM35	Row42 Row43	RAM42 RAM43	Row34 Row35	RAM42 RAM43	
COM		Row36	RAM36	Row44	RAM44	Row36	RAM44	Row36	RAM36	Row44	RAM44	Row36	RAM44	
COM		Row37	RAM37	Row45	RAM45	Row37	RAM45	Row37	RAM37	Row45	RAM45	Row37	RAM45	
COMS		Row38 Row39	RAM38 RAM39	Row46 Row47	RAM46 RAM47	Row38 Row39	RAM46 RAM47	Row38 Row39	RAM38 RAM39	Row46 Row47	RAM46 RAM47	Row38 Row39	RAM46 RAM47	
COM4	40 F	Row40	RAM40	Row48	RAM48	Row40	RAM48	Row40	RAM40	Row48	RAM48	Row40	RAM48	
COM ²		Row41 Row42	RAM41 RAM42	Row49 Row50	RAM49 RAM50	Row41 Row42	RAM49 RAM50	Row41 Row42	RAM41 RAM42	Row49 Row50	RAM49 RAM50	Row41 Row42	RAM49 RAM50	
COM ²	43 F	Row43	RAM43	Row51	RAM51	Row43	RAM51	Row43	RAM43	Row51	RAM51	Row43	RAM51	
COM ²		Row44 Row45	RAM44 RAM45	Row52 Row53	RAM52 RAM53	Row44 Row45	RAM52 RAM53	Row44 Row45	RAM44 RAM45	Row52 Row53	RAM52 RAM53	Row44 Row45	RAM52 RAM53	
COM4	16 F	Row46	RAM46	Row54	RAM54	Row46	RAM54	Row46	RAM46	Row54	RAM54	Row46	RAM54	
COM ²		Row47 Row48	RAM47 RAM48	Row55 Row56	RAM55 RAM56	Row47 Row48	RAM55 RAM56	Row47 Row48	RAM47 RAM48	Row55	RAM55	Row47 Row48	RAM55 RAM56	
COM2		Row49	RAM49	Row57	RAM57	Row49	RAM57	Row49	RAM49	-	-	Row49	RAM57	
COM		Row50	RAM50	Row58	RAM58	Row50	RAM58	Row50	RAM50	-	-	Row50	RAM58	
COM		Row51 Row52	RAM51 RAM52	Row59 Row60	RAM59 RAM60	Row51 Row52	RAM59 RAM60	Row51 Row52	RAM51 RAM52	-	-	Row51 Row52	RAM59 RAM60	
COM	53 F	Row53	RAM53	Row61	RAM61	Row53	RAM61	Row53	RAM53	-	-	Row53	RAM61	
COM		Row54 Row55	RAM54 RAM55	Row62 Row63	RAM62 RAM63	Row54 Row55	RAM62 RAM63	Row54 Row55	RAM54 RAM55	-	-	Row54 Row55	RAM62 RAM63	
COM	56 F	Row56	RAM56	Row0	RAM0	Row56	RAM0	-	-	Row0	RAM0	-	-	
COM		Row57 Row58	RAM57 RAM58	Row1 Row2	RAM1 RAM2	Row57 Row58	RAM1 RAM2	-	-	Row1 Row2	RAM1 RAM2	-	-	
COM	59 F	Row59	RAM59	Row3	RAM3	Row59	RAM3	-	-	Row3	RAM3	-	-	
COM		Row60 Row61	RAM60 RAM61	Row4 Row5	RAM4 RAM5	Row60 Row61	RAM4 RAM5	-	-	Row4 Row5	RAM4 RAM5	-	-	
COM		Row62	RAM62	Row6	RAM6	Row62	RAM6	-	-	Row6	RAM6	-	-	
COM6 Display		Row63	RAM63	Row7	RAM7	Row63	RAM7	-	-	Row7	RAM7	-	-	
example		(8	a)	(1	0)	(c)	(0	d)	(e)	(f)	J
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			(e)			(1)					(RA	AM)	

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Table 10-2: Example of Set Display Offset and Display Start Line with Remap

Part									tput							<u> </u>
Hardware																,
Company Comp	Hardware						_						_			
CALCAL PROMES PARKS PA			-						-							
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COUNT From														-		
COLUMB Flower Profess Profes														_		
C.C.M.C. Prof. P										_				-		
CLUBS FlowEs Fl	COMP	How58	KAM58	How2	HAM2	How58	HAM2	How42	HAM42	-	-	How42	HAMb0	-	-	j
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COMES PANSE PANS																l
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COM/SS ROWG RANGS ROWG RANGS ROWG RANGS RANGS	COM26	Row37	RAM37	Row45	RAM45		RAM45	Row21	RAM21	Row29	RAM29	Row21	RAM29	Row29	RAM45	
C.2.M.25 Prox/31 Prox/32 Prox/34 Prox/32 Prox/34 Prox/35 Pr																
C.J.M.G. PowGS PANGS PowG PANGS PowG PANGS PANG PanGS PANG																
COMES RANKES RA																1
C.2.M.SS	COM31	Row32	RAM32	Row40	RAM40	Row32	RAM40	Row16	RAM16	Row24	RAM24	Row16	RAM24	Row24	RAM40	
COMGS Row28 RAM29 Row37 RAM37 Row28 RAM36 Row18 RAM31 Row21 RAM21 Row21 RAM21 Row22 RAM36 Row38 Raw38 Row38 Raw38 Row39 Row39 Raw38 Row39 Raw39 Row39 Raw38 Row39 Raw38 Row39 Raw38 Row39 Raw39 Row39 Raw38 Row39 Raw39 Row39 Raw38 Row39 Raw39 Raw3																
COMSS HOW28 RAMC8 RAMC8 RAMC8 RAMC8 HOW25 HAMC5 HAMC																
COM65 NowZ NAME Name Name Name Name Name																1
COM88 RowZ5 RAMZ5 RowZ3 RAMZ5 RowZ5 RAMZ5 ROWZ																
COUM40 HOW24 HAMZ4 HOW25 HAMS2 HOW24 HAMS2 HOW8 HAMB HOW16 HAM16 HOW16 HAM16 HOW16 HAM52 COUM40 HOW23 RAM23 RAM31 RAM31 ROW2 RAM30 HOW25 RAM30 HOW26 RAM30 HOW26 RAM30 HOW27 HAM29 HOW21 HAM29 HOW21 HAM29 HOW21 HAM29 HOW26 HAM313 HAM329 HOW26 HAM30 HAM20 HOW28 RAM30 HOW26 HAM30 HAM30																
COMM0																l
COM41 Row22 RAM22 RAM22 RAM30 RAM20 RAM29 RAM22 RAM30 RAM6 RAM6 RAM6 RAM13																Y.
COM44 Row19 RAW20 RAW28 RAW28 RAW28 Row20 RAW28 Row4 RAW4 Row12 RAW11 Row3 RAW11 RAW11 Row3 RAW11																
COM44																
COMM6																
COM46 Row17 RAM17 Row25 RAW25 Row17 RAW25 Row1 RAM1 Row9 RAM9 Row1 RAM9 Row9 RAW25 Row18 RAW25 Row16 RAW24 RAW24 RAW24 Row16 RAW24 RAW24 RAW24 RAW24 RAW24 RAW24 RAW24 RAW25 RAW									_							k
COM47 Row16 RAM16 Row24 RAM24 Row16 RAM24 Row0 RAM0 RAM0 RAM8 Row0 RAM8 Row8 RAM24 RAM24 RAM23 RAM23 RAM23 RAM23 RAM24 RAM24 RAM24 RAM24 RAM25 RAM24 RAM25 RAM																l e
COM49 Row14 RAM14 Row22 RAW22 Row14 RAW21 Row6 RAW6 Row6 RAW22 COM50 Row13 RAM13 Row21 RAW21 RAW21 Row6 RAW6 Row6 RAW21 RAW22 RAW2 RAW2 RAW2 RAW2 RAW2 RAW2 RAW	COM47				RAM24		RAM24	Row0	RAM0			Row0	RAM8		RAM24	ĺ
COM50 Row13 RAM13 Row21 RAW21 Row13 RAW21 Row6 RAW5 Row6 RAW21 COM51 How12 HAW12 HAW12 HAW12 HAW12 How4 HAW14 How4 HAW12 HAW12 COM53 Row10 RAW11 HOW19 HAW19 HOW1 RAW19 HOW1 RAW15 How3 HAW3 Row2 RAW18 COM53 Row10 RAW19 How1 HAW1 How9 HAW1 How3 HAW1 Row2 RAW18 COM56 Row8 HAW19 How1 HAW1 How1 HAW1 Row2 RAW18 COM56 Row8 HAW18 Row16 HAW16 How1 HAW1 How1 HAW1 How1 HAW1 Row1 HAW1 Row1 HAW1 How1 HAW1 How1 HAW1 How0 HAW16 COM56 Row7 RAW17 Row15 RAW15 Row8 RAW15								-	-			-	-			l
CUM51								_				_				l e
COM52 How11 HAM11 How19 HAM19 How11 HAM19 How3 HAM3 How3 HAM19 How11 How10 HAM10 How4 HAM2 How4 HAM10 HAM11 How9 HAM11 How9 HAM11 How9 HAM11 How9 HAM10 How1 HAM10 How1 HAM11 HAM11 How9 HAM11 How9 HAM11 How9 HAM10 How1 HAM10 How1 HAM11 HAM11 How9 HAM16 How8 HAM16 How8 HAM16 How8 HAM16 How0 HAM00 How0 HAM10 HAM116 How8 HAM16 How8 HAM16 How8 HAM16 How8 HAM16 How8 HAM16 How16 HAM16 How8 HAM16 How14 HAM114 How6 HAM16 How12 HAM11 How6 HAM16 How12 HAM11 How4 HAM10 HAM10 How4 HAM10 HAM10 HOW4 HAM10 HAM10 HAM10 HAM10 HAM10 HAM10 HAM10 HAM10 HAM1								-				-				i .
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COM66 How8 HAM8 How16 HAM16 How8 HAM16 How0 HAM10 How0 HAM16 COM66 How7 RAM17 How15 RAM15 Row7 RAM15								-	-			-	-			
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COM57 Row6 RAM6 Row14 RAM14 Row6 RAM14								_	-		- I I/-IIVIO		-		-	i e
COM59 Row4 RAM4 Row12 RAM12 Row4 RAM12								-	-	-	-	-	-	-	-	ĺ
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CUM61 How2 HAM2 How10 HAM10 How2 HAM10								-	-	-	-	-	-	-	-	l
COM62								_	-	_	-	_	-	_	-	l e
COM63 Row0 RAM0 Row8 RAM8 Row0 RAM8 Display (a) (b) (c) (d) (e) (f) (g)								-	-	-	-	-	-	-	-	ì
		Row0	RAM0	Row8	RAM8	Row0	RAM8	-	-	-	-	-	-	-	-	j
lexamples C C C C C C C C C	Display	-	(a)	(b)		c)	(d)		e)	(:	f)	6	g)	
	examples	,	/	(-,	(-,	(/	,	-,	(-	-,	· ·	D)	J



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10.1.16 Set Display Clock Divide Ratio/ Oscillator Frequency (D5h)

This command consists of two functions:

- Display Clock Divide Ratio (D)(A[3:0])
 Set the divide ratio to generate DCLK (Display Clock) from CLK. The divide ratio is from 1 to 16, with reset value = 1. Please refer to section 8.3 for the details relationship of DCLK and CLK.
- Oscillator Frequency (A[7:4])
 Program the oscillator frequency Fosc that is the source of CLK if CLS pin is pulled high. The 4-bit value results in 16 different frequency settings available as shown below. The default setting is 1000b.

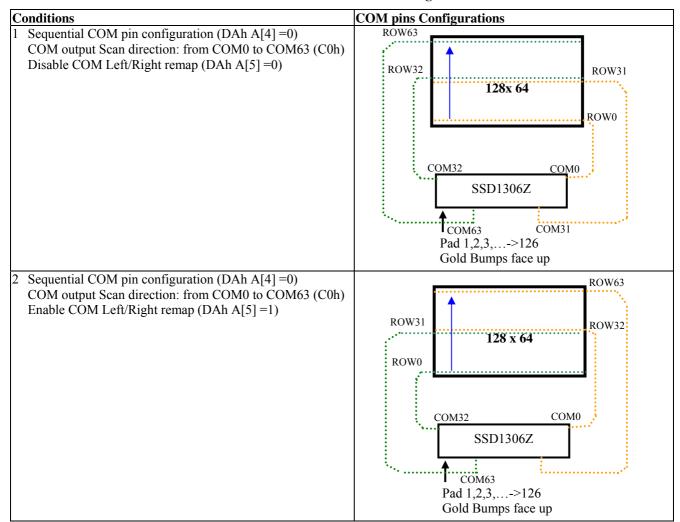
10.1.17 Set Pre-charge Period (D9h)

This command is used to set the duration of the pre-charge period. The interval is counted in number of DCLK, where RESET equals 2 DCLKs.

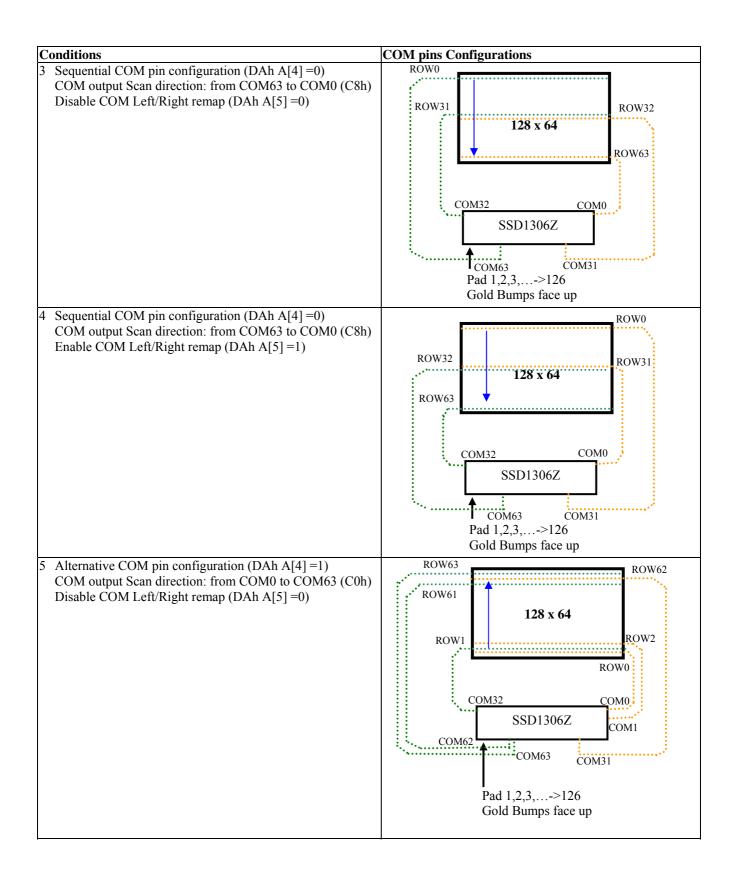
10.1.18 Set COM Pins Hardware Configuration (DAh)

This command sets the COM signals pin configuration to match the OLED panel hardware layout. The table below shows the COM pin configuration under different conditions (for MUX ratio =64):

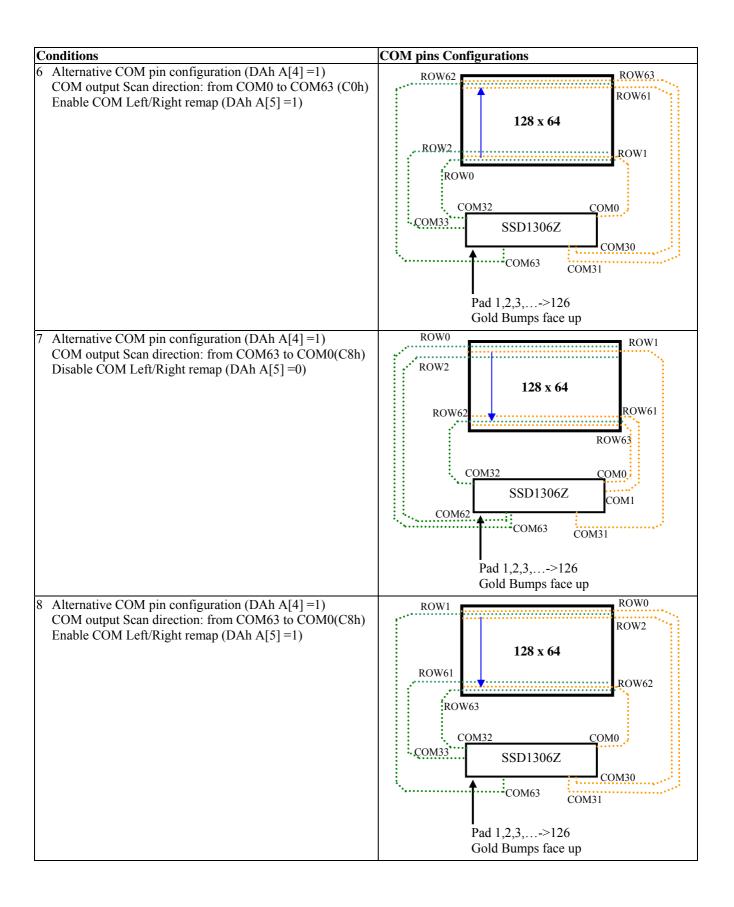
Table 10-3: COM Pins Hardware Configuration



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10.1.19 Set V_{COMH} Deselect Level (DBh)

This command adjusts the V_{COMH} regulator output.

10.1.20 NOP (E3h)

No Operation Command

10.1.21 Status register Read

This command is issued by setting D/C# ON LOW during a data read (See Figure 13-1 to Figure 13-2 for parallel interface waveform). It allows the MCU to monitor the internal status of the chip. No status read is provided for serial mode.

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10.2 Graphic Acceleration Command

10.2.1 Horizontal Scroll Setup (26h/27h)

This command consists of consecutive bytes to set up the horizontal scroll parameters and determines the scrolling start page, end page and scrolling speed.

Before issuing this command the horizontal scroll must be deactivated (2Eh). Otherwise, RAM content may be corrupted.

The SSD1306 horizontal scroll is designed for 128 columns scrolling. The following two figures (Figure 10-7, Figure 10-8, Figure 10-9) show the examples of using the horizontal scroll:

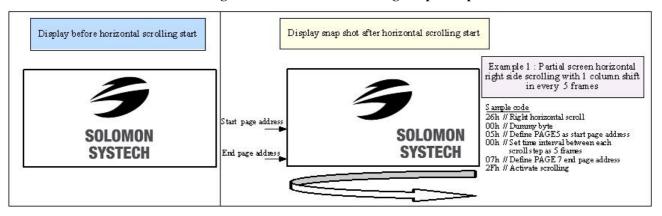
Figure 10-7: Horizontal scroll example: Scroll RIGHT by 1 column

Original Setting	SEG0	SEG1	SEG2	SEG3	SEG4	SEG5	:	÷	:	SEG122	SEG123	SEG124	SEG125	SEG126	SEG127
After one scroll step	SEG127	SEG0	SEG1	SEG2	SEG3	SEG4	:	:	:	SEG121	SEG122	SEG123	SEG124	SEG125	SEG126

Figure 10-8: Horizontal scroll example: Scroll LEFT by 1 column

Original Setting	SEG0	SEG1	SEG2	SEG3	SEG4	SEG5	:	 :	SEG122	SEG123	SEG124	SEG125	SEG126	SEG127
After one scroll step	SEG1	SEG2	SEG3	SEG4	SEGS	SEG6	::	 	SEG123	SEG124	SEG125	SEG126	SEG127	SEG0

Figure 10-9: Horizontal scrolling setup example



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10.2.2 Continuous Vertical and Horizontal Scroll Setup (29h/2Ah)

This command consists of 6 consecutive bytes to set up the continuous vertical scroll parameters and determines the scrolling start page, end page, scrolling speed and vertical scrolling offset.

The bytes B[2:0], C[2:0] and D[2:0] of command 29h/2Ah are for the setting of the continuous horizontal scrolling. The byte E[5:0] is for the setting of the continuous vertical scrolling offset. All these bytes together are for the setting of continuous diagonal (horizontal + vertical) scrolling. If the vertical scrolling offset byte E[5:0] is set to zero, then only horizontal scrolling is performed (like command 26/27h).

Before issuing this command the scroll must be deactivated (2Eh). Otherwise, RAM content may be corrupted. The following figure (Figure 10-10) show the example of using the continuous vertical and horizontal scroll:

Example 1 : Full screen diagonal Display before scrolling start Display snap shot after scrolling start scrolling (horizontal right side scrolling with 1 column shift plus Start page address/ vertical scrolling with 1 row up) in every 6 frames. No. of rows in top fixed area =0 (POR) Sample code 29h // Vertical and right horizontal scroll No. of rows in scroll 00h // Dummybyte 00h // Define PAGEO as start page address 00h // Set time interval between each area =64 (POR) scroll step as 6 frames 07h // Define PAGE7 as end page address End page address Olh #Set vertical scrolling offset as 1 row 2Fh // Activate scrolling

Figure 10-10: Continuous Vertical and Horizontal scrolling setup example

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10.2.3 Deactivate Scroll (2Eh)

This command stops the motion of scrolling. After sending 2Eh command to deactivate the scrolling action, the ram data needs to be rewritten.

10.2.4 Activate Scroll (2Fh)

This command starts the motion of scrolling and should only be issued after the scroll setup parameters have been defined by the scrolling setup commands: 26h/27h/29h/2Ah. The setting in the last scrolling setup command overwrites the setting in the previous scrolling setup commands.

The following actions are prohibited after the scrolling is activated

- 1. RAM access (Data write or read)
- 2. Changing the horizontal scroll setup parameters

10.2.5 Set Vertical Scroll Area(A3h)

This command consists of 3 consecutive bytes to set up the vertical scroll area. For the continuous vertical scroll function (command 29/2Ah), the number of rows that in vertical scrolling can be set smaller or equal to the MUX ratio.

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11 MAXIMUM RATINGS

Table 11-1: Maximum Ratings (Voltage Referenced to VSS)

Symbol	Parameter	Value	Unit
$V_{ m DD}$	Supply Voltage	-0.3 to +4	V
V_{CC}	Supply voltage	0 to 16	V
V_{SEG}	SEG output voltage	0 to V _{CC}	V
V_{COM}	COM output voltage	0 to 0.9*V _{CC}	V
V _{in}	Input voltage	V_{SS} -0.3 to V_{DD} +0.3	V
T_A	Operating Temperature	-40 to +85	°C
T_{stg}	Storage Temperature Range	-65 to +150	°C

Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics tables or Pin Description section

This device may be light sensitive. Caution should be taken to avoid exposure of this device to any light source during normal operation. This device is not radiation protected.

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12 DC CHARACTERISTICS

Condition (Unless otherwise specified):

Voltage referenced to V_{SS} $V_{DD} = 1.65$ to 3.3V $T_A = 25$ °C

Table 12-1: DC Characteristics

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V_{CC}	Operating Voltage	-	7	-	15	V
$V_{ m DD}$	Logic Supply Voltage	-	1.65	_	3.3	V
V_{OH}	High Logic Output Level	$I_{OUT} = 100uA, 3.3MHz$	$0.9 \times V_{DD}$	-	-	V
V_{OL}	Low Logic Output Level	$I_{OUT} = 100uA, 3.3MHz$	-	-	$0.1 \times V_{DD}$	V
V_{IH}	High Logic Input Level	-	$0.8 \times V_{DD}$	-	-	V
$ m V_{IL}$	Low Logic Input Level	-	-	-	0.2 x V_{DD}	V
I _{CC, SLEEP}	I _{CC,} Sleep mode Current	V_{DD} = 1.65V \sim 3.3V, V_{CC} = 7V \sim 15V Display OFF, No panel attached	-	-	10	uA
I _{DD, SLEEP}	I _{DD,} Sleep mode Current	V_{DD} = 1.65V~3.3V, V_{CC} = 7V~15V Display OFF, No panel attached	-	-	10	uA
I_{CC}	V_{CC} Supply Current V_{DD} = 2.8V, V_{CC} = 12V, I_{REF} = 12.5uA No loading, Display ON, All ON	Contrast = FFh	-	430	780	uA
${ m I_{DD}}$	V_{DD} Supply Current V_{DD} = 2.8V, V_{CC} = 12V, I_{REF} = 12.5uA No loading, Display ON, All ON		-	50	150	uA
	Segment Output Current	Contrast=FFh	-	100	_	
I_{SEG}	V_{DD} =2.8V, V_{CC} =12V,	Contrast=AFh	-	69	-	uA
	I _{REF} =12.5uA, Display ON.	Contrast=3Fh	-	25	-	
Dev	Segment output current uniformity	$\begin{aligned} & \text{Dev} = (I_{\text{SEG}} - I_{\text{MID}}) / I_{\text{MID}} \\ & I_{\text{MID}} = (I_{\text{MAX}} + I_{\text{MIN}}) / 2 \\ & I_{\text{SEG}}[0:131] = \text{Segment current at} \\ & \text{contrast} = FFh \end{aligned}$	-3	-	+3	%
Adj. Dev	Adjacent pin output current uniformity (contrast = FF)	Adj Dev = $(I[n]-I[n+1]) / (I[n]+I[n+1])$	-2	-	+2	%

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13 AC CHARACTERISTICS

Conditions:

 $\begin{aligned} &Voltage \ referenced \ to \ V_{SS} \\ &V_{DD} = 1.65 \ to 3.3 V \\ &T_A = 25 ^{\circ} C \end{aligned}$

Table 13-1: AC Characteristics

•	Parameter	Test Condition	Min	Тур	Max	Unit
Fosc (1)	Oscillation Frequency of Display	$V_{DD} = 2.8V$	333	370	407	kHz
	Timing Generator					
FFRM	Frame Frequency for 64 MUX	128x64 Graphic Display Mode,	-	F _{OSC} x 1/(DxKx64)	-	Hz
	Mode	Display ON, Internal Oscillator		(2)		
		Enabled				
RES#	Reset low pulse width		3	-	-	us

Note

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 $^{^{(1)}}$ Fosc stands for the frequency value of the internal oscillator and the value is measured when command D5h A[7:4] is in default value.

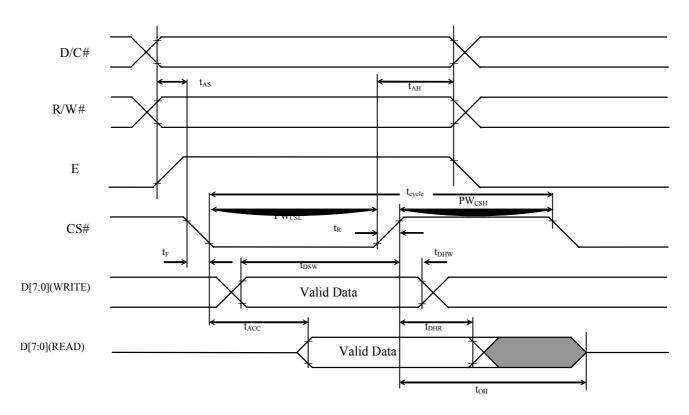
 ⁽²⁾ D: divide ratio (default value = 1)
 K: number of display clocks (default value = 54)
 Please refer to Table 9-1 (Set Display Clock Divide Ratio/Oscillator Frequency, D5h) for detailed description

Table 13-2: 6800-Series MCU Parallel Interface Timing Characteristics

 $(V_{DD} - V_{SS} = 1.65 \text{V to } 3.3 \text{V}, T_A = 25 ^{\circ}\text{C})$

Symbol	Parameter	Min	Тур	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	0	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
$t_{\rm DHW}$	Write Data Hold Time	7	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t _{OH}	Output Disable Time	-	-	70	ns
t _{ACC}	Access Time	-	-	140	ns
PW _{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW _{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t_R	Rise Time	-	-	40	ns
$t_{\rm F}$	Fall Time	-	-	40	ns

Figure 13-1: 6800-series MCU parallel interface characteristics



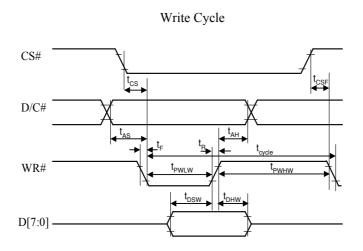
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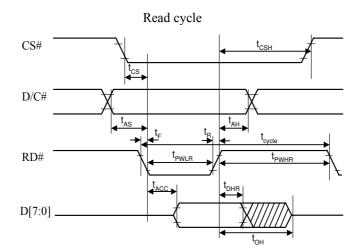
Table 13-3: 8080-Series MCU Parallel Interface Timing Characteristics

 $(V_{DD} - V_{SS} = 1.65 \text{V to } 3.3 \text{V}, T_A = 25^{\circ}\text{C})$

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	10	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
$t_{ m DHW}$	Write Data Hold Time	7	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t _{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
t_{PWLR}	Read Low Time	120	-	-	ns
t_{PWLW}	Write Low Time	60	-	-	ns
t_{PWHR}	Read High Time	60	-	-	ns
t_{PWHW}	Write High Time	60	-	-	ns
t_R	Rise Time	-	-	40	ns
$t_{\rm F}$	Fall Time	-	-	40	ns
t _{CS}	Chip select setup time	0	-	_	ns
t _{CSH}	Chip select hold time to read signal	0	-	-	ns
t _{CSF}	Chip select hold time	20	-	-	ns

Figure 13-2: 8080-series parallel interface characteristics





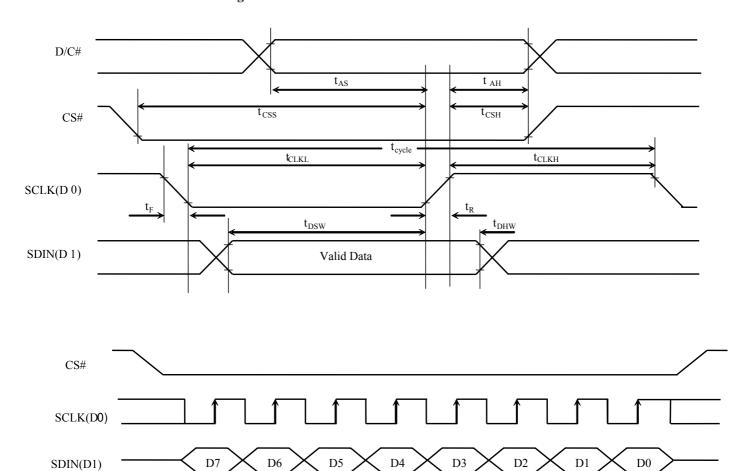
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Table 13-4 : 4-wire Serial Interface Timing Characteristics

 $(V_{DD} - V_{SS} = 1.65 \text{V to } 3.3 \text{V}, T_A = 25 ^{\circ}\text{C})$

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	100	-	-	ns
t_{AS}	Address Setup Time	15	-	-	ns
t_{AH}	Address Hold Time	15	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	10	-	-	ns
$t_{ m DSW}$	Write Data Setup Time	15	-	-	ns
$t_{ m DHW}$	Write Data Hold Time	15	-	-	ns
$t_{ m CLKL}$	Clock Low Time	20	-	-	ns
$t_{ m CLKH}$	Clock High Time	20	-	-	ns
t_{R}	Rise Time	_	_	40	ns
t_{F}	Fall Time	-	-	40	ns

Figure 13-3: 4-wire Serial interface characteristics



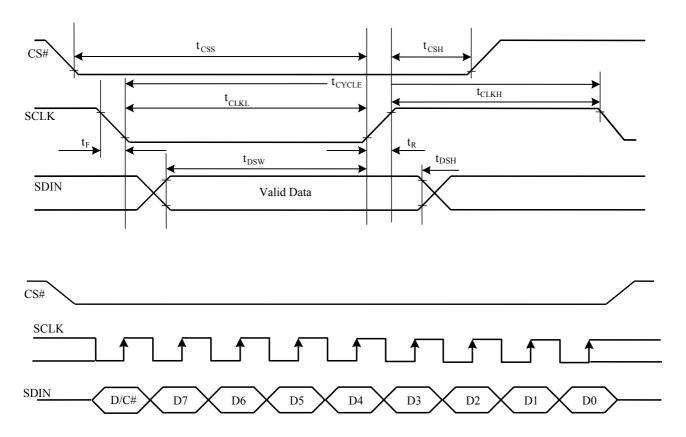
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Table 13-5: 3-wire Serial Interface Timing Characteristics

 $(V_{DD} - V_{SS} = 1.65V \text{ to } 3.3V, T_A = 25^{\circ}C)$

Symbol	Parameter	Min	Тур	Max	Unit
t_{cycle}	Clock Cycle Time	100	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	10	-	-	ns
t_{DSW}	Write Data Setup Time	15	-	-	ns
t_{DHW}	Write Data Hold Time	15	-	-	ns
t_{CLKL}	Clock Low Time	20	-	-	ns
t_{CLKH}	Clock High Time	20	-	-	ns
t_R	Rise Time	-	-	40	ns
$t_{\rm F}$	Fall Time	-	-	40	ns

Figure 13-4: 3-wire Serial interface characteristics



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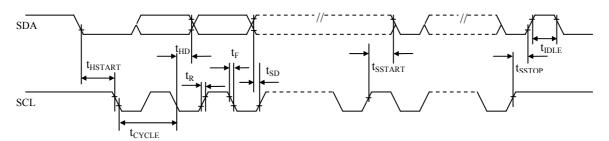
Conditions:

$$V_{\rm DD}$$
 - $V_{\rm SS}$ = $V_{\rm DD}$ - $V_{\rm SS}$ = 1.65V to 3.3V $T_{\rm A}$ = 25°C

Table 13-6: I²C Interface Timing Characteristics

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	2.5	-	-	us
t _{HSTART}	Start condition Hold Time	0.6	-	-	us
$t_{ m HD}$	Data Hold Time (for "SDA _{OUT} " pin)	0	-	-	ns
	Data Hold Time (for "SDA _{IN} " pin)	300	-	-	ns
t_{SD}	Data Setup Time	100	-	-	ns
t_{SSTART}	Start condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	-	us
t_{SSTOP}	Stop condition Setup Time	0.6	-	-	us
t _R	Rise Time for data and clock pin	-	-	300	ns
$t_{\rm F}$	Fall Time for data and clock pin	-	-	300	ns
$t_{ m IDLE}$	Idle Time before a new transmission can start	1.3	-	-	us

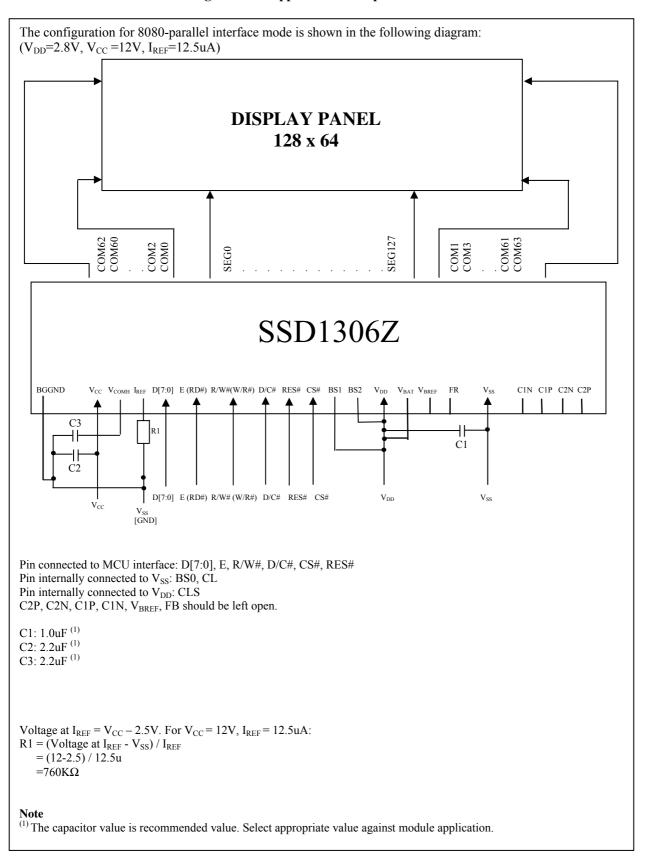
Figure 13-5: I²C interface Timing characteristics



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14 Application Example

Figure 14-1: Application Example of SSD1306Z

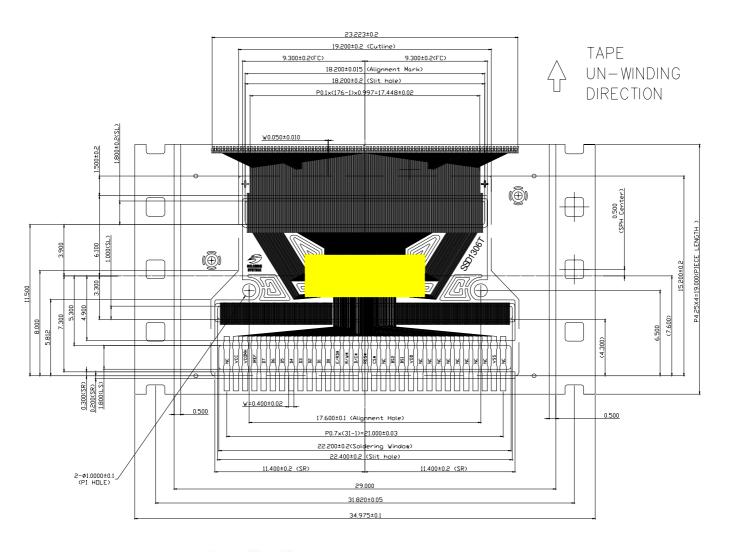


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15 PACKAGE INFORMATION

15.1 SSD1306TR1 Detail Dimension

Figure 15-1 SSD1306TR1 Detail Dimension



Specification:

1. GENERAL TOLERANCE: ±0.05 mm

2.MATERIAL

PI: 75 ± 8 um CU: 15 ± 3 um

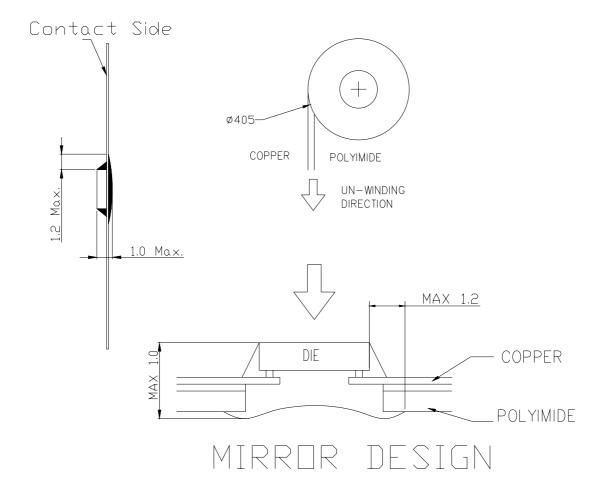
ADHESIVE: 12 ± 3um

SR: 26 ± 14 um

TOLERANCE ± 0.200 mm

FLEX COATING: Min10 um 3.Plating: Sn 0.20 ±0.05 um 4. TAPESITE: 4 SPH,19 mm

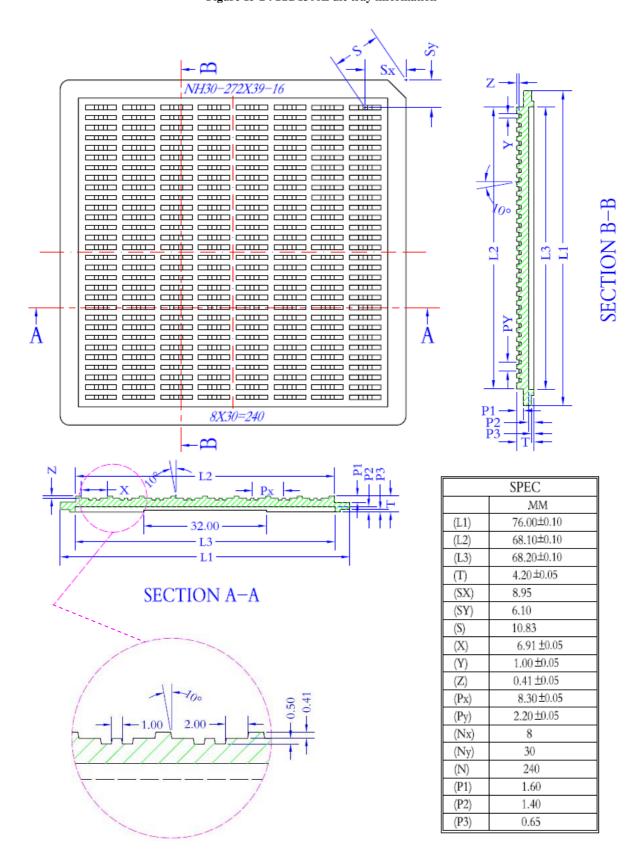
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15.2 SSD1306Z Die Tray Information

Figure 15-2: SSD1306Z die tray information



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SSD1306

Application Note

128 x 64 Dot Matrix
OLED/PLED Segment/Common Driver with Controller

This document contains information on a new product. Specifications and information herein are subject to change without notice.



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1 Introduction

This application note of SSD1306 is written to explain the charge pump regulator function of SSD1306. SSD1306 is a single-chip CMOS OLED/PLED driver with controller for organic / polymer light emitting diode dot-matrix graphic display system. It consists of 128 segments and 64 commons. This IC is designed for Common Cathode type OLED panel.

For the detailed characteristics of the driver IC, please refer to SSD1306 datasheet.

2 Charge Pump Regulator

The internal regulator circuit in SSD1306 accompanying only 2 external capacitors can generate a 7.5V voltage supply, V_{CC} , from a low voltage supply input, V_{BAT} . The V_{CC} is the voltage supply to the OLED driver block. This is a switching capacitor regulator circuit, designed for handheld applications. This regulator can be turned on/off by software command setting.

Power supply

o $V_{DD} = 1.65V$ to 3.3V, $< V_{BAT}$ for IC logic

 \circ V_{BAT} = 3.3V to 4.2V for charge pump regulator circuit

· Pins description for related pins of the charge pump regulator

V_{BAT} – Power supply for charge pump regulator circuit.

D/ (I			
Status	V_{BAT}	V_{DD}	Vcc
Enable	Connect to external	Connect to external	A capacitor should be connected
charge pump	V _{BAT} source	V _{DD} source	between this pin and V _{SS}
Disable	Connect with V _{DD}	Connect to external	Connect to external V _{CC} source
charge pump	pin	V _{DD} source	

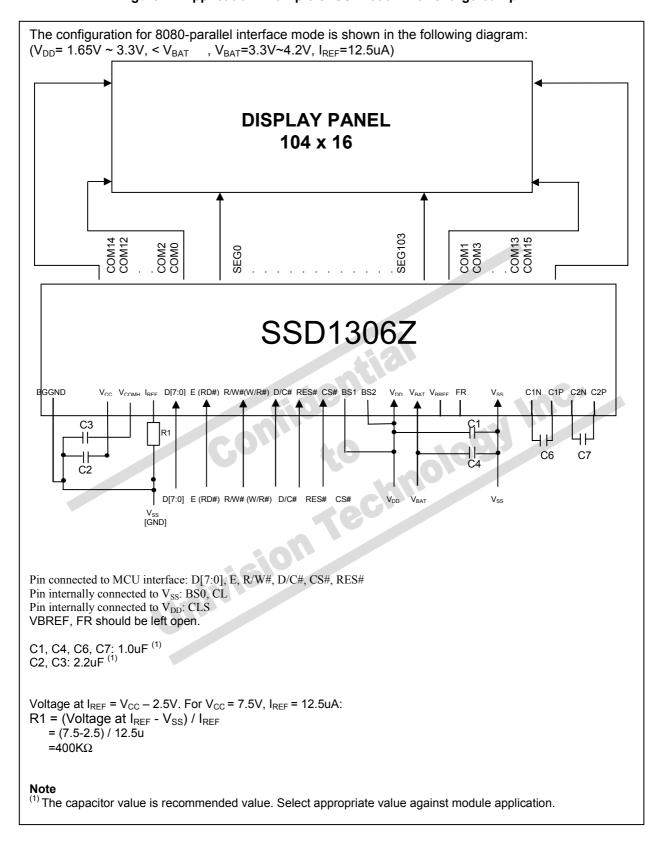
- o C1P/C1N Pin for charge pump capacitor; Connect to each other with a capacitor
- o C2P/C2N Pin for charge pump capacitor; Connect to each other with a capacitor

2.1 Command Table for Charge Bump Setting

1. Ch	1. Charge Pump Command Table										
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	8D	1	0	0	0	1	1	0	1	_	A[2] = 0b, Disable charge
0	A[7:0]	*	*	0	1	0	A_2	0	0		pump(RESET)
											A[2] = 1b, Enable charge pump
											during display on
											Note (1) The Charge Pump must be enabled by the following command: 8Dh; Charge Pump Setting 14h; Enable Charge Pump AFh; Display ON

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Figure 1: Application Example of SSD1306Z with charge bump



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3 Software Configuration

SSD1306 has internal command registers that are used to configure the operations of the driver IC. After reset, the registers should be set with appropriate values in order to function well. The registers can be accessed by MPU interface in either 6800, 8080, SPI type with D/C# pin pull low or using I²C interface. Below is an example of initialization flow of SSD1306. The values of registers depend on different condition and application.

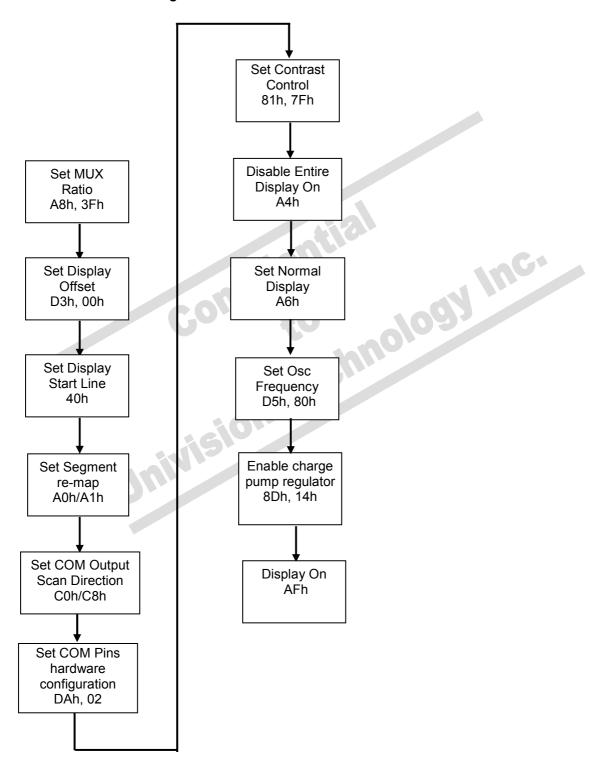


Figure 2 : Software Initialization Flow Chart

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